

Doris Eckstein (CMS)

8. October 2024





This is not an up-to-date status of radiation damage status

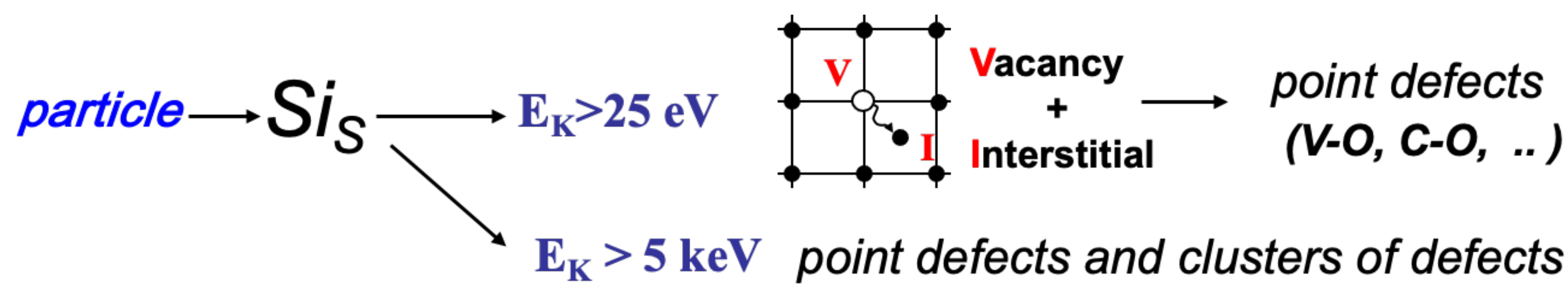
There are people which to-day work on these topics

My aim is

- to give an introduction to radiation damage applicable to the silicon sensors currently used at the LHC
- to motivate the usage of n-in-p at HL-LHC
- to raise awareness that models are phenomenological descriptions and the defects used therein are not actual defects in silicon
- to raise awareness that acceptor-removal and donor-removal are simplifications of what actually happens in the lattice



- Particles passing through silicon material loose energy through
 - interaction with shell electrons (Ionizing Energy Loss)
 - surface damage
 - local charges accumulate in surface
(charges cannot recombine in insulating surface
- amorphous Si, SiO₂-
thus it causes damage in the surface)
 - damage caused primarily through photons, charged particles
 - this is used for particle detection
 - fast recombination in silicon bulk → no damage in the bulk
 - interaction with atomic core or whole atom (Non Ionizing Energy Loss)
 - bulk damage
 - Displacement of atoms in the lattice
 - Caused by massive particles as protons, pions, neutrons

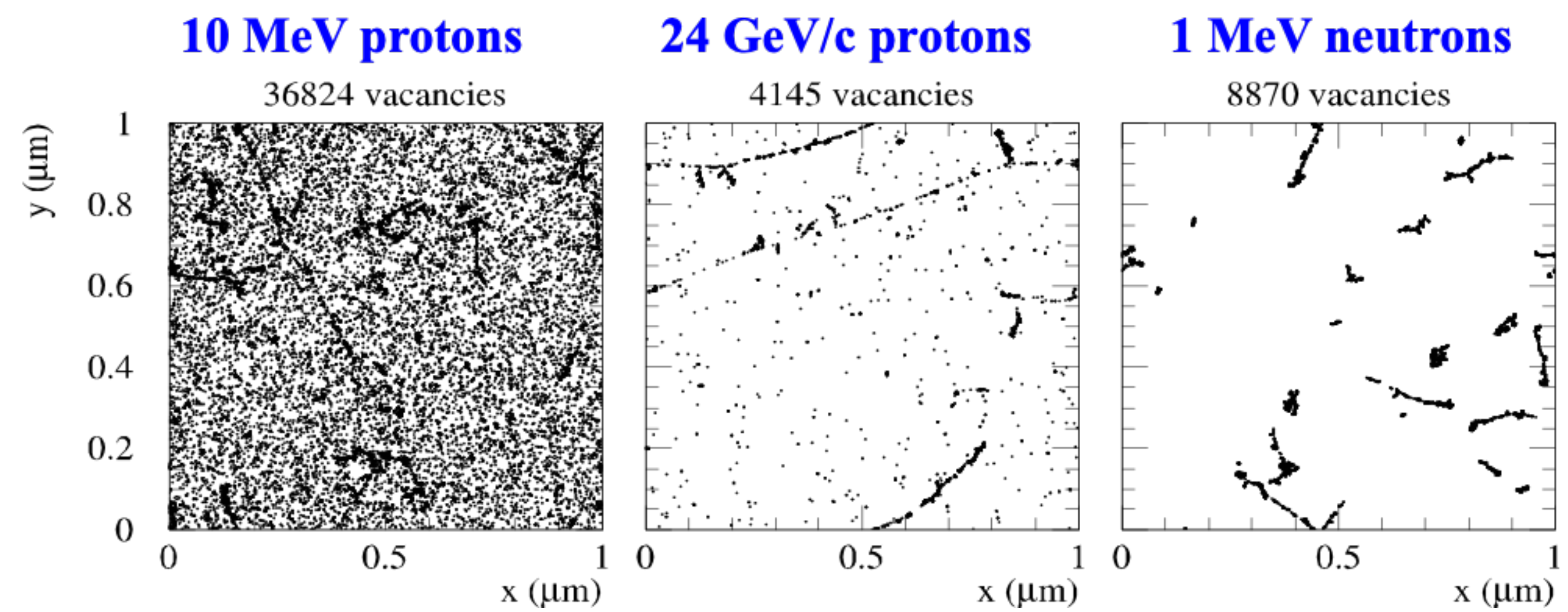


- | | | |
|---|---|---|
| <ul style="list-style-type: none">• ^{60}Co-gammas• Compton Electrons with max. $E_\gamma \approx 1 \text{ MeV}$ (no cluster production) | <ul style="list-style-type: none">• Electrons• $E_e > 255 \text{ keV}$ for displacement• $E_e > 8 \text{ MeV}$ for cluster | <ul style="list-style-type: none">• Neutrons (elastic scattering)• $E_n > 185 \text{ eV}$ for displacement• $E_n > 35 \text{ keV}$ for cluster |
| Only point defects ↔ point defects & clusters ↔ Mainly clusters | | |

Simulation:

Initial distribution of vacancies in $(1\mu\text{m})^3$ after $10^{14} \text{ particles/cm}^2$

[Mika Huhtinen NIMA 491(2002) 194]



NIEL scaling

- **NIEL - Non Ionizing Energy Loss** scaling using hardness factors of a radiation field (or monoenergetic particle) with respect to 1 MeV neutrons

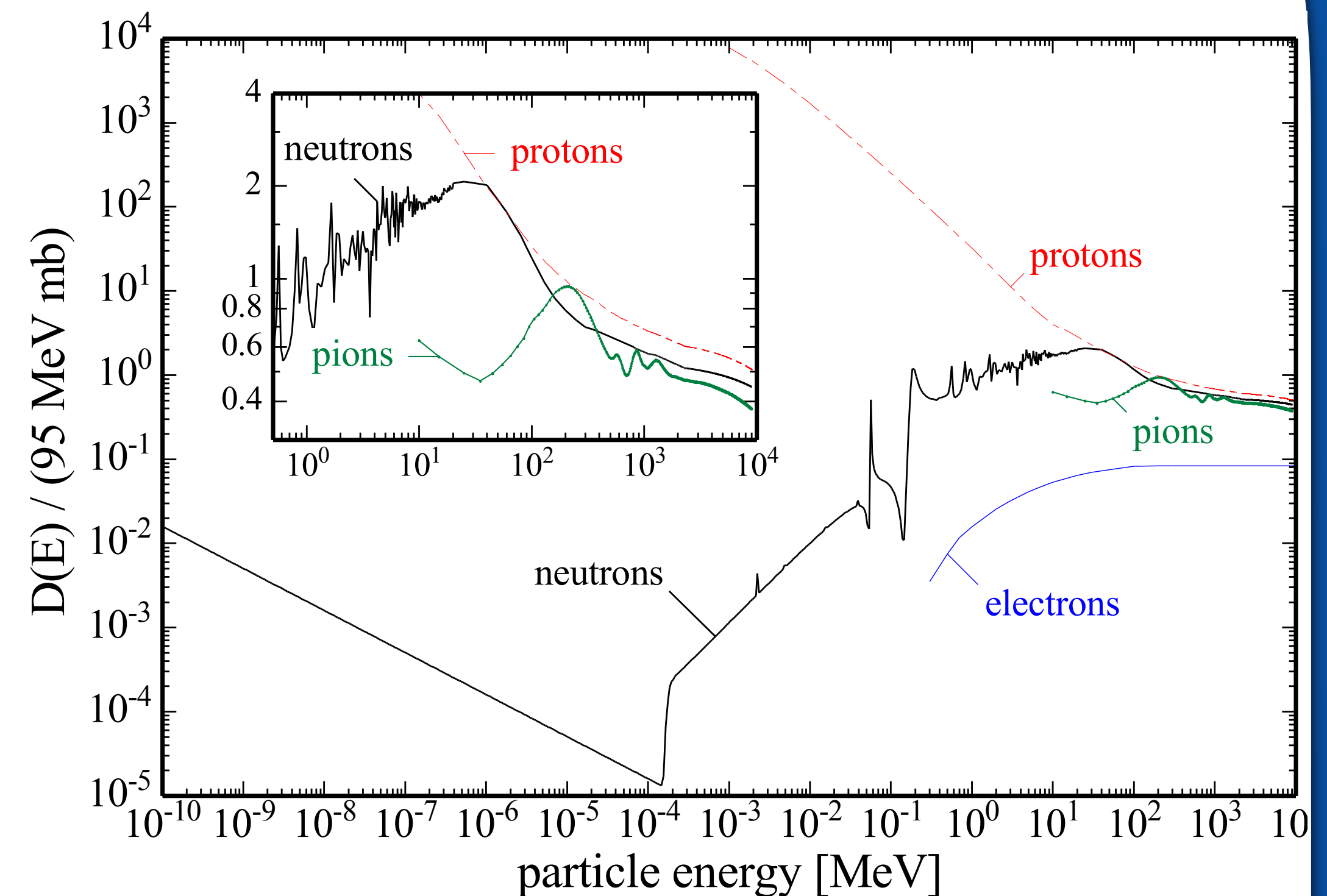
$$\kappa = \frac{1}{D(1\text{MeV neutrons})} \cdot \frac{\int D(E) \phi(E) dE}{\int \phi(E) dE}$$

- **E** energy of particle
- **D(E)** displacement damage cross section for a certain particle at energy E
D(1MeV neutrons)=95 MeV·mb
- **φ(E)** energy spectrum of radiation field

The integrals are evaluated for the interval $[E_{\text{MIN}}, E_{\text{MAX}}]$, being E_{MIN} and E_{MAX} the minimum and maximum cut-off energy values, respectively, and covering all particle types present in the radiation field

- **NIEL - Non Ionizing Energy Loss**
- **NIEL - Hypothesis: Damage parameters scale with the NIEL**
 - *Be careful, does not hold for all particles & damage parameters (see later)*

N_{eq} fluence hardness factors for reactor neutrons: 0.91, for 23GeV protons 0.62



Poisson's equation

$$-\frac{d^2}{dx^2}\phi(x) = \frac{q_0}{\epsilon\epsilon_0} \cdot N_{eff}$$

with $\frac{d}{dx}\phi(x=w) = 0$
 $\phi(x=w) = 0$

$$-\frac{d}{dx}\phi(x) = \frac{q_0}{\epsilon\epsilon_0} \cdot N_{eff} \cdot (x-w)$$

$$\phi(x) = \frac{1}{2} \cdot \frac{q_0}{\epsilon\epsilon_0} \cdot N_{eff} \cdot (x-w)^2$$

depletion voltage

$$V_{dep} = \frac{q_0}{2\epsilon\epsilon_0} \cdot |N_{eff}| \cdot d^2$$

w = depletion depth

d = detector thickness

U = voltage

N_{eff} = effective doping concentration

$$C = \frac{dQ}{dU} = \frac{dQ \cdot dw}{dw \cdot dU}$$

$$w(U) = \sqrt{\frac{2\epsilon\epsilon_0}{q_0 |N_{eff}|} \cdot U}$$

$$C(U) = A \cdot \sqrt{\frac{\epsilon\epsilon_0 q_0 |N_{eff}|}{2U}}$$

$$C(w) = \frac{\epsilon\epsilon_0 A}{w}$$

Measurements with diodes

Standard experiments:

- Irradiations with p , n , γ , π

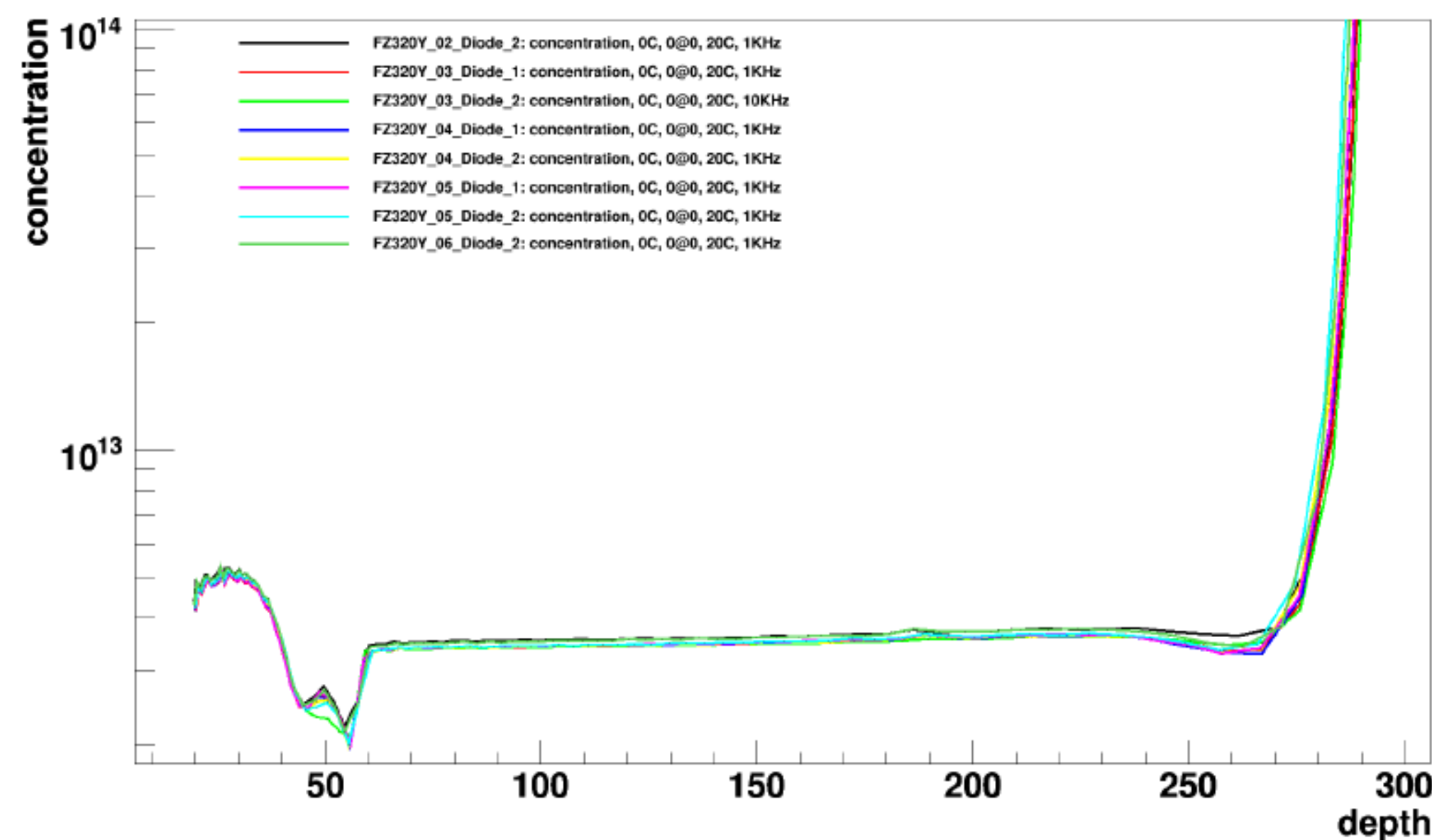
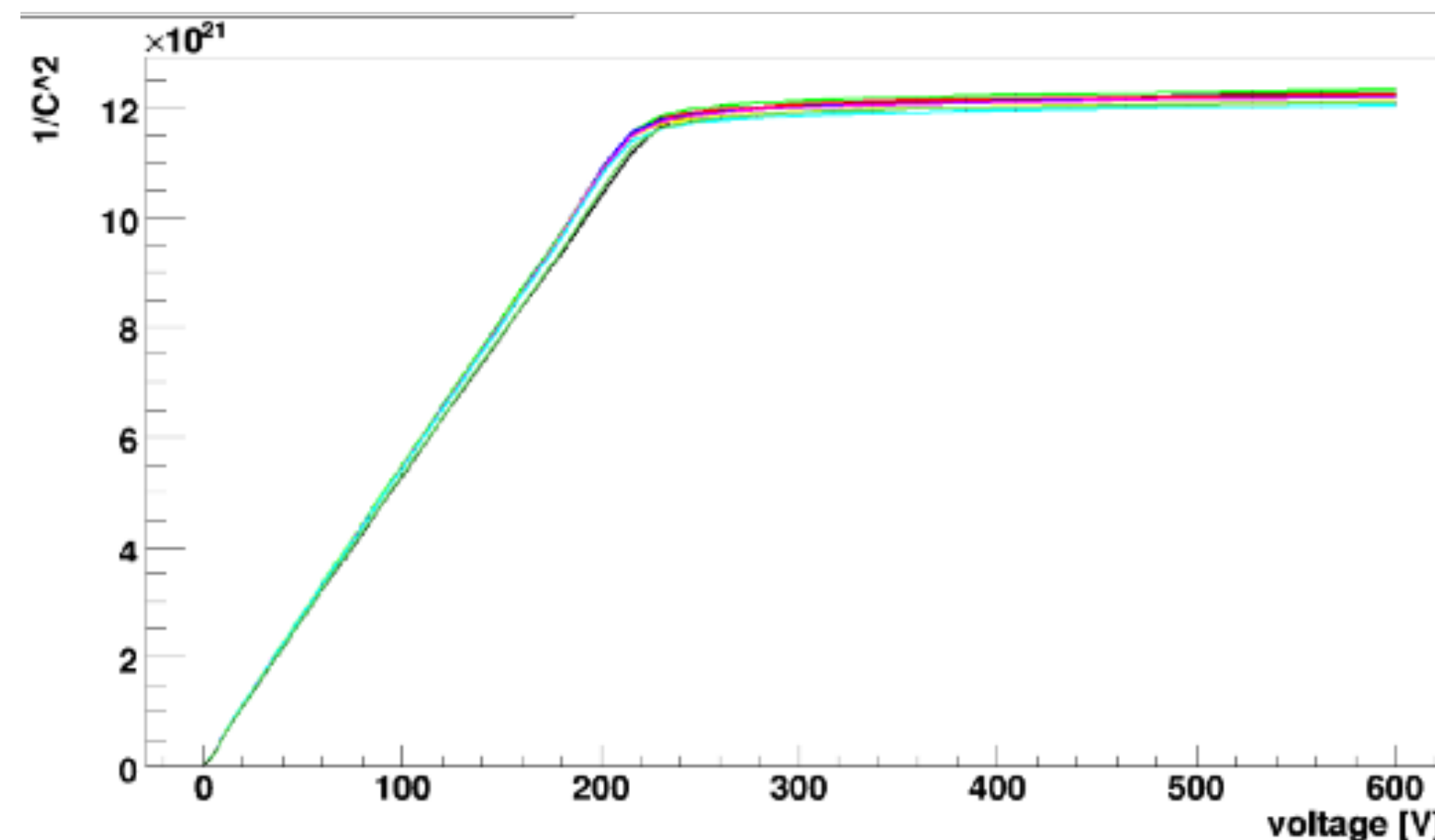
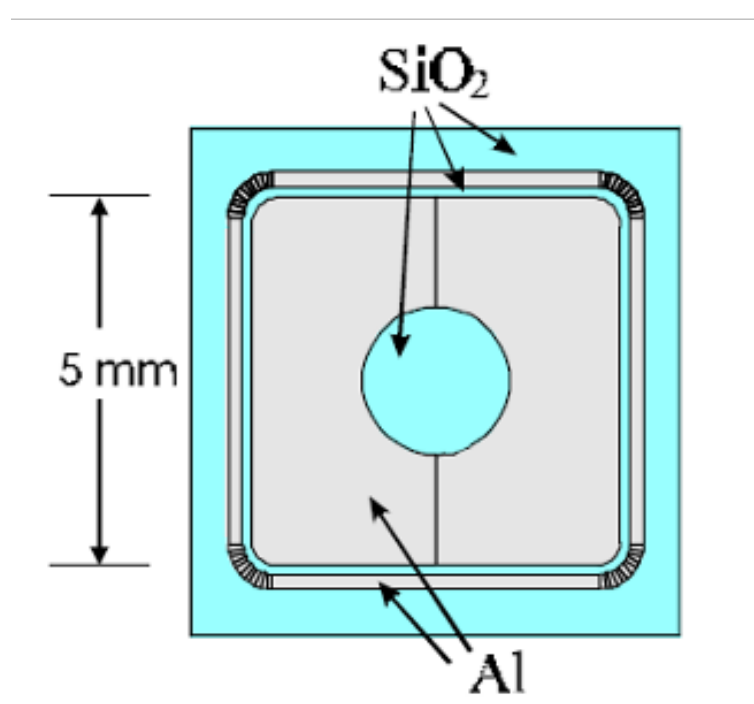
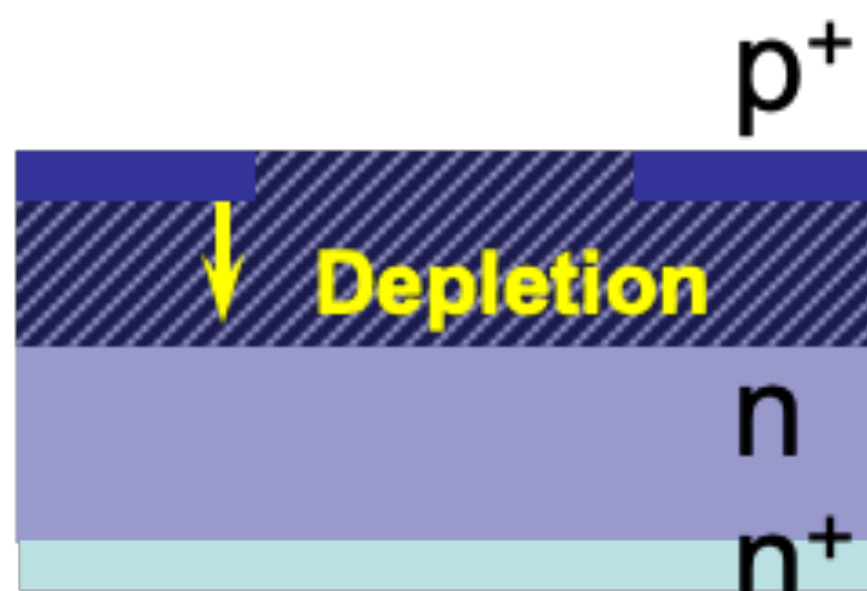
Measurements:

- CV measurements $\rightarrow V_{\text{dep}} \sim N_{\text{eff}}$
- IV measurements $\rightarrow I_{\text{leak}}$ at V_{dep}
- Laser (TCT) measurements $\rightarrow$ Charge Collection
- DLTS and TSC $\rightarrow$ microscopic defects

Annealing:

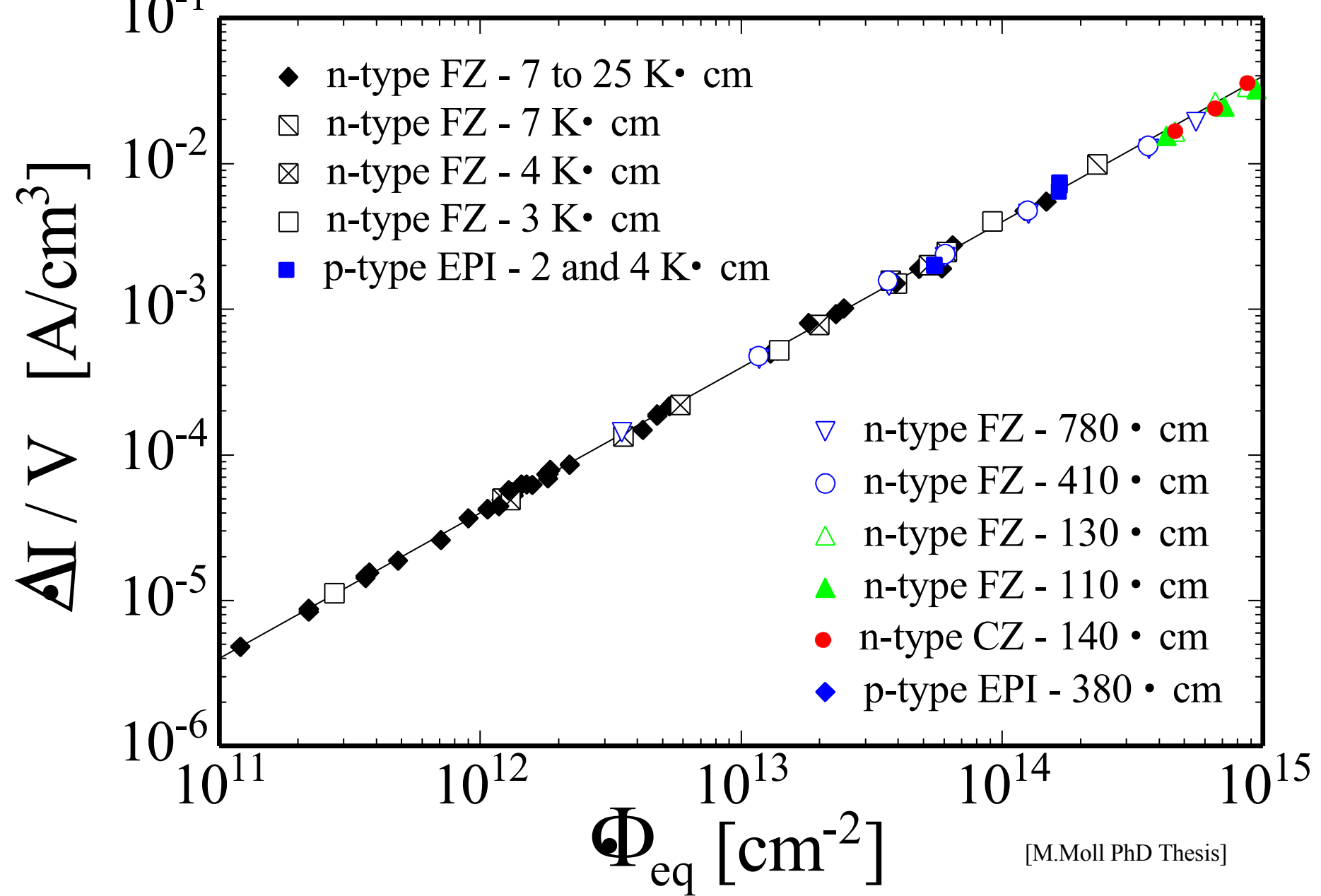
Isochronal and isothermal

- $\rightarrow$ learn about defect parameters
- $\rightarrow$ damage scenarios for LHC



Change of leakage current

.... with particle fluence:



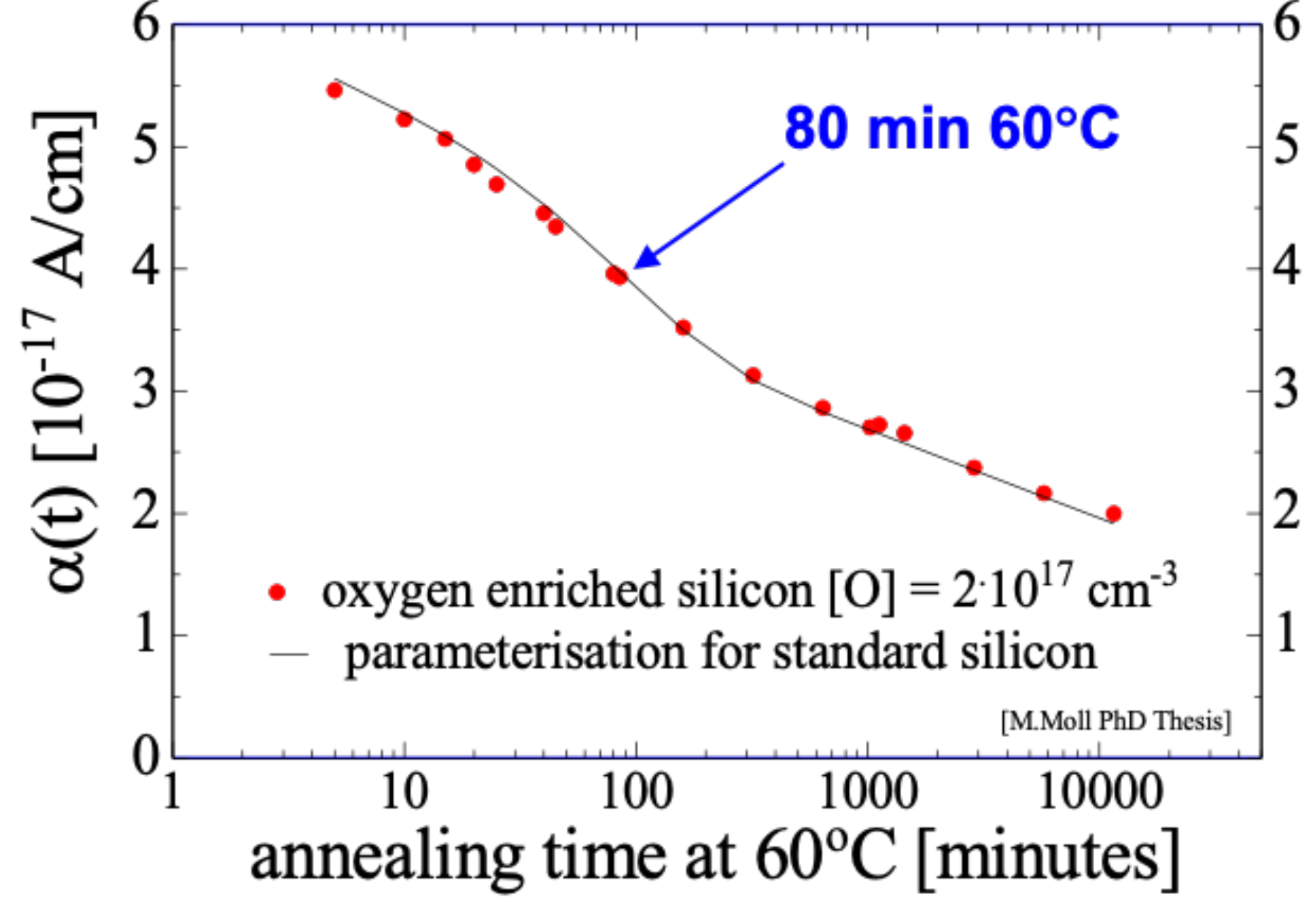
- **Damage parameter α (slope in figure)**

$$\alpha = \frac{\Delta I}{V \cdot \Phi_{eq}}$$

**Leakage current
per unit volume
and particle fluence**

- **α is constant over several orders of fluence and independent of impurity concentration in Si**
- **⇒ can be used for fluence measurement!**

.... with time (annealing):



- **Leakage current decreasing in time (depending on temperature)**
- **Strong temperature dependence**

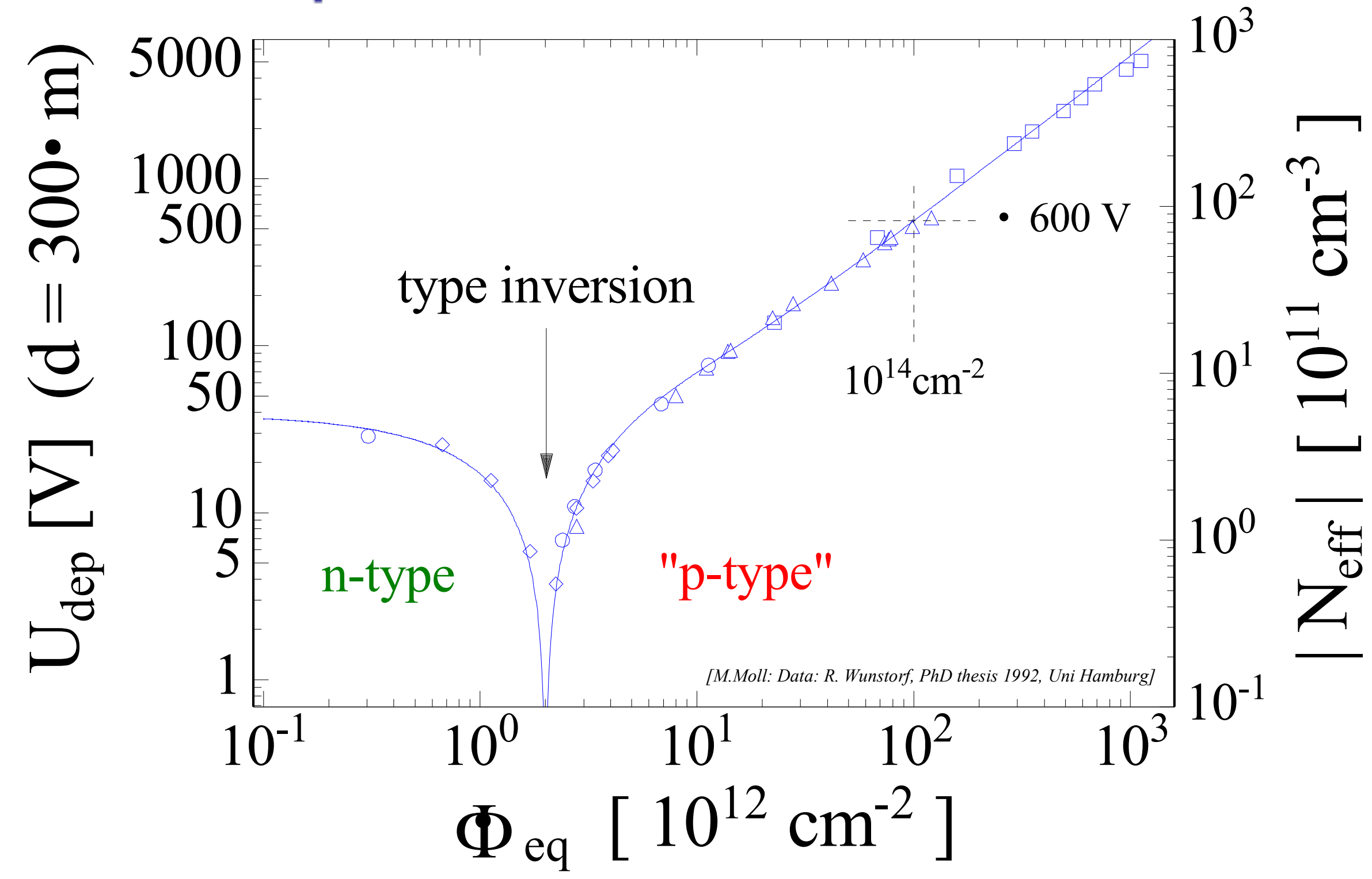
$$I \propto \exp\left(-\frac{E_g}{2k_B T}\right)$$

Consequence:

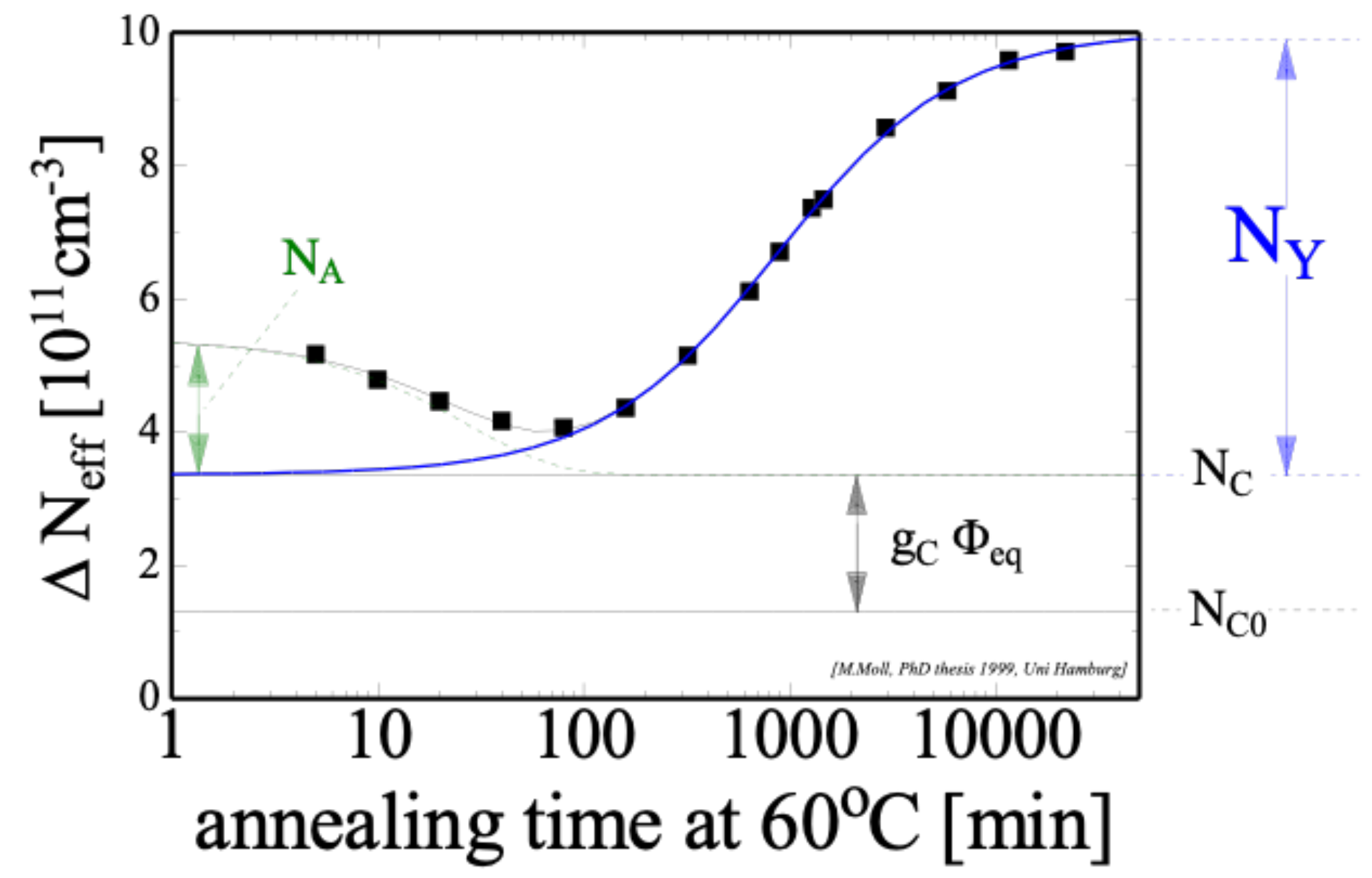
Cool detectors during operation!
Example: $I(-10^\circ\text{C}) \sim 1/16 I(20^\circ\text{C})$



.... with particle fluence:



.... with time (annealing):



- **“Type inversion”**: N_{eff} changes from positive to negative (Space Charge Sign Inversion)

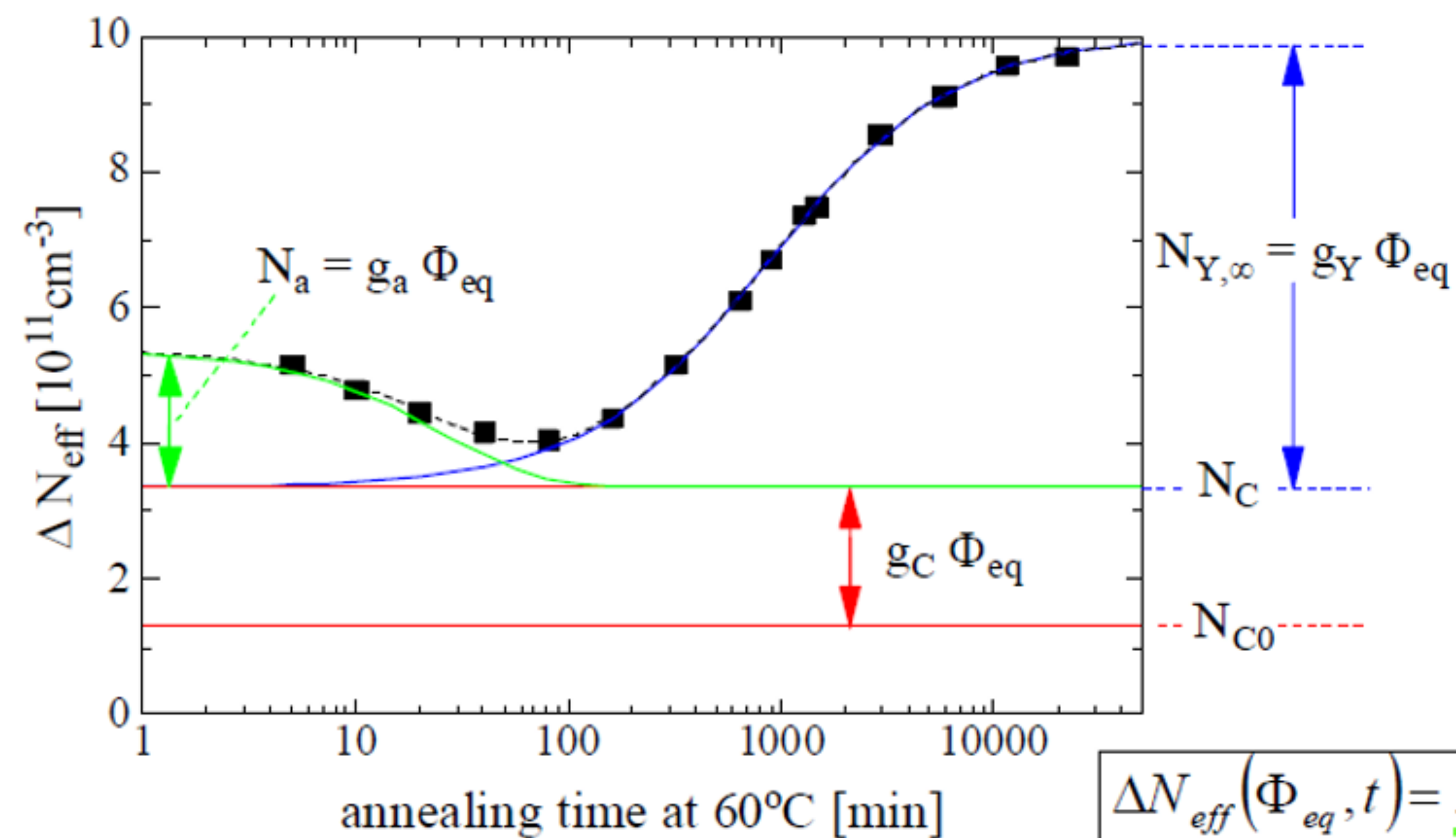
- Short term: **“Beneficial annealing”**
- Long term: **“Reverse annealing”**
 - time constant depends on temperature:
 - ~ 500 years (-10°C)
 - ~ 500 days (20°C)
 - ~ 21 hours (60°C)
 - Consequence: **Detectors must be cooled even when the experiment is not running!**



Annealing behavior of N_{eff} - Hamburg model -

$$\Delta N_{\text{eff}}(\Phi_{\text{eq}}, t) = N_{\text{eff}0} - N_{\text{eff}}(\Phi_{\text{eq}}, t)$$

ΔN_{eff} = Change of N_{eff} with respect to $N_{\text{eff}0}$ (value before irradiation)



long term reverse annealing:

$$N_Y = N_{Y,\infty} \cdot \left(1 - \frac{1}{1 + t/\tau_y} \right)$$

second order parameterization (with $N_{y,\infty} = g_y \times \Phi_{\text{eq}}$). gives best fit
But:
 τ_y independent of Φ_{eq}
 $\Rightarrow$ underlying defect reaction based on **first order** process!

$$\Delta N_{\text{eff}}(\Phi_{\text{eq}}, t) = \underbrace{N_a(\Phi_{\text{eq}}, t)}_{\text{green}} + \underbrace{N_c(\Phi_{\text{eq}})}_{\text{red}} + \underbrace{N_y(\Phi_{\text{eq}}, t)}_{\text{blue}}$$

short term annealing:

$$N_a = \Phi_{\text{eq}} \times \sum_i g_{ai} \times \exp\left(-t/\tau_i\right)$$

first order decay of acceptors introduced proportional to Φ_{eq} during irradiation

stable damage:

$$N_c = N_{c0} \cdot (1 - \exp(-c \cdot \Phi_{\text{eq}})) + g_c \cdot \Phi_{\text{eq}}$$

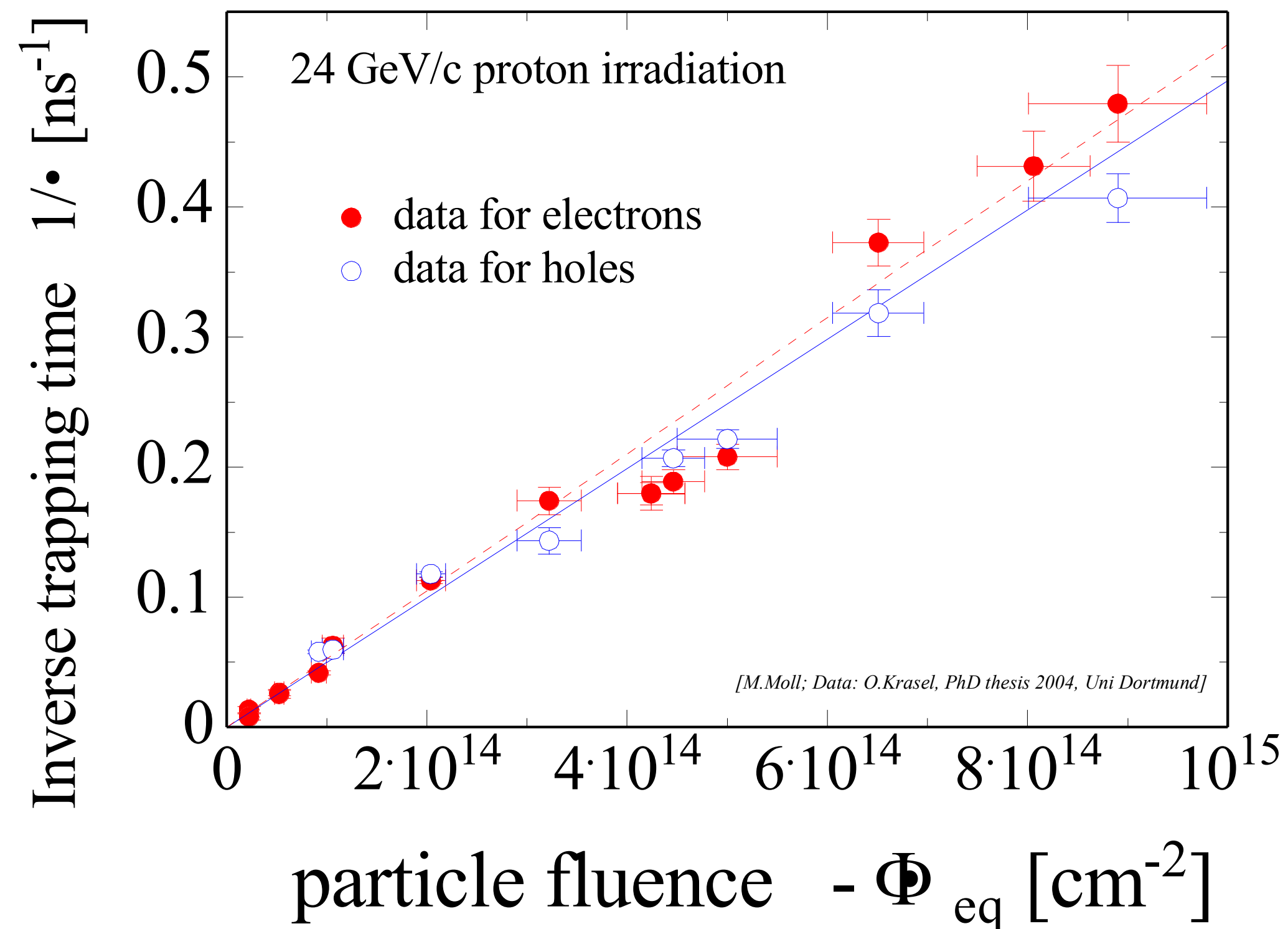
incomplete „donor removal“
+ introduction of stable acceptors

■ Deterioration of Charge Collection Efficiency (CCE) by trapping

Trapping is characterized by an effective trapping time τ_{eff} for electrons and holes:

$$Q_{e,h}(t) = Q_{0e,h} \exp\left(-\frac{1}{\tau_{\text{eff } e,h}} \cdot t\right) \quad \text{where} \quad \frac{1}{\tau_{\text{eff } e,h}} \propto N_{\text{defects}}$$

Increase of inverse trapping time ($1/\tau$) with fluence

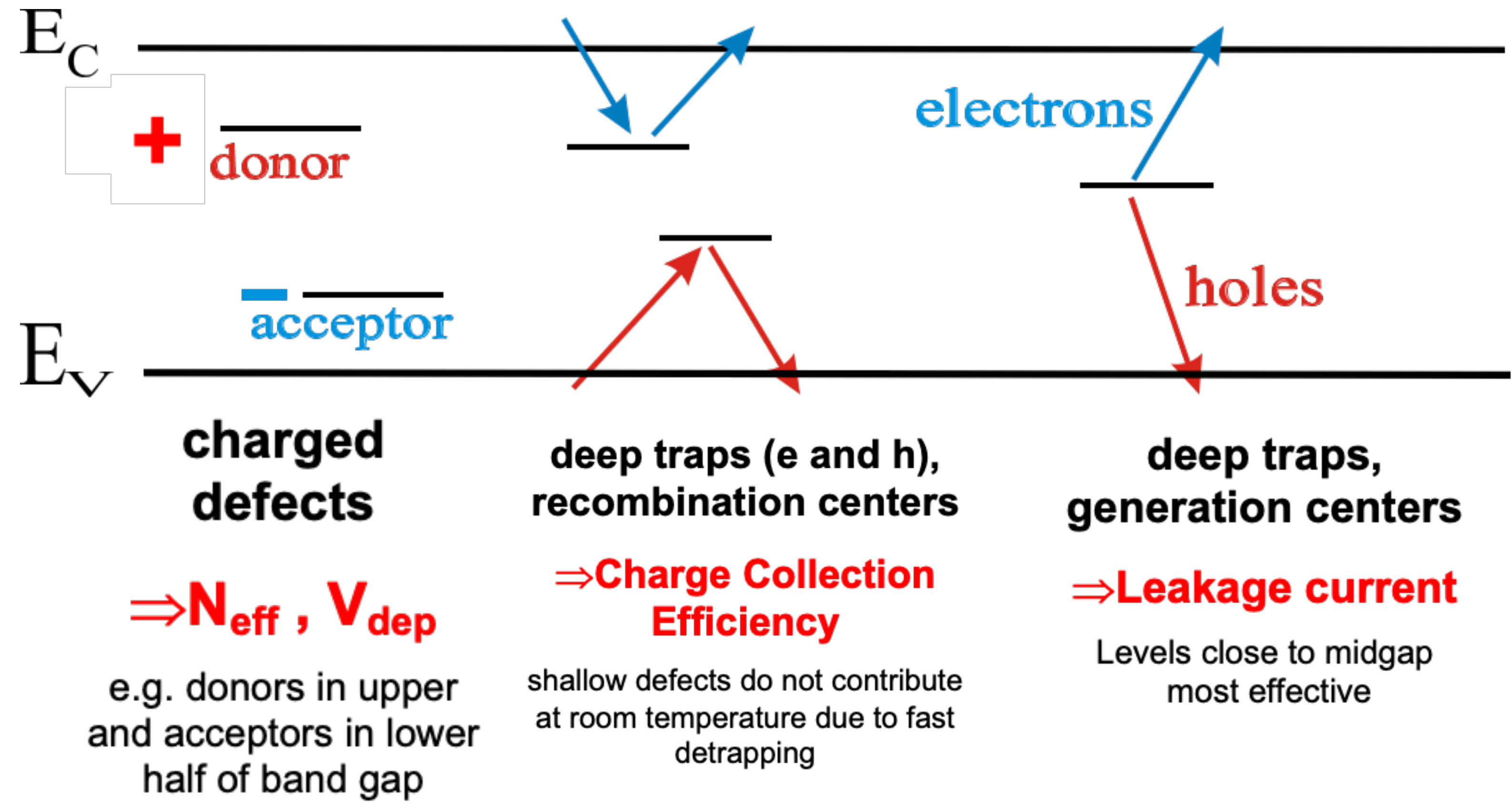


drift velocity of electrons > drift velocity of holes

—> electron collection is beneficial

Change of detector properties

- defects in the crystal
- point defects and “cluster” defects
- ➔ energy levels in the band gap filled



Impact on detector properties can be calculated if all defect parameters are known:

$\sigma_{n,p}$: cross sections ΔE : ionization energy N_t : concentration



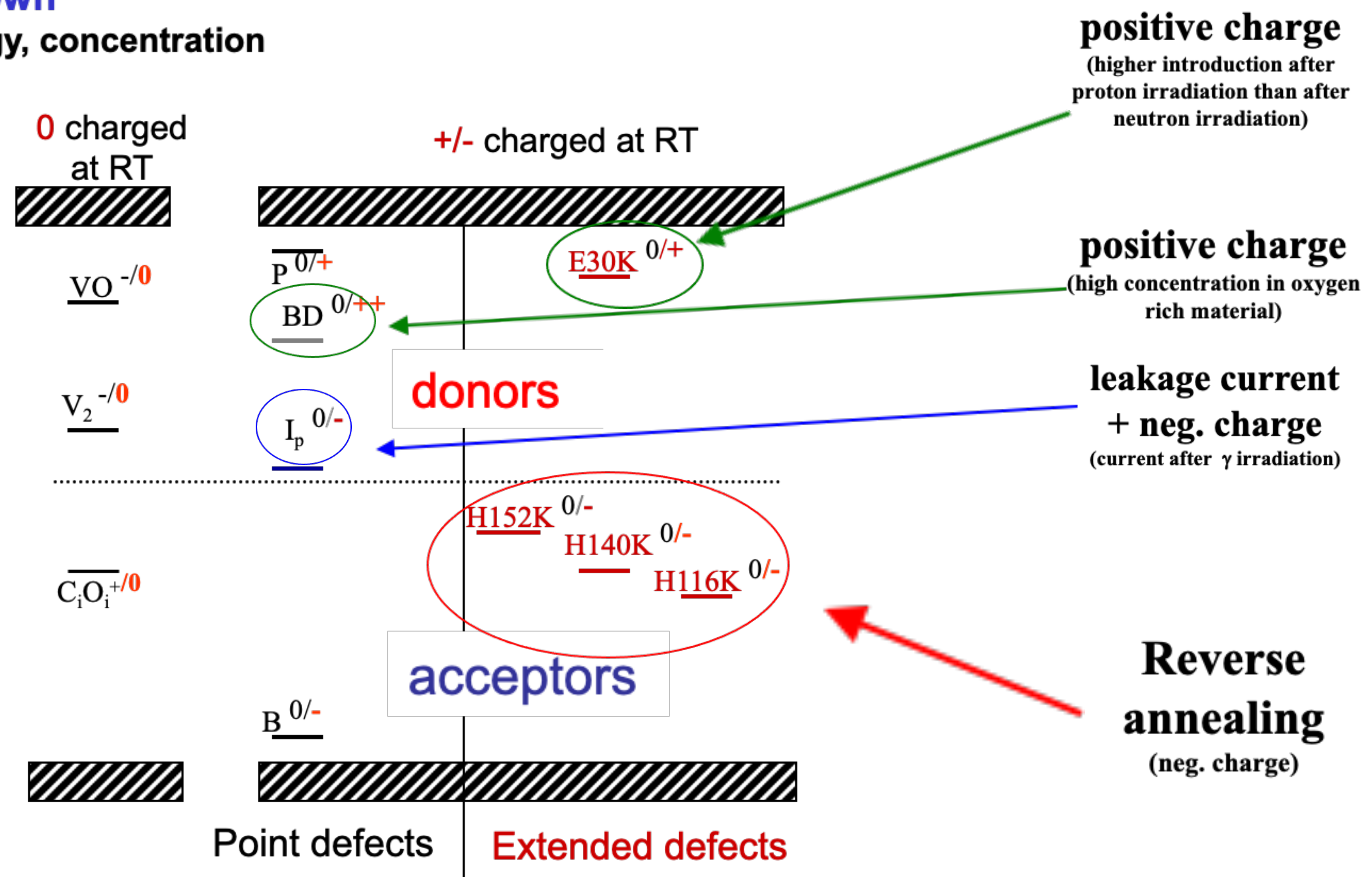
- Calculate/Simulate effect on device properties if all defect parameters are known
 - cross section, ionization energy, concentration

Point defects

- $E_i^{BD} = E_c - 0.225 \text{ eV}$
- $\sigma_n^{BD} = 2.3 \cdot 10^{-14} \text{ cm}^2$
- $E_i^I = E_c - 0.545 \text{ eV}$
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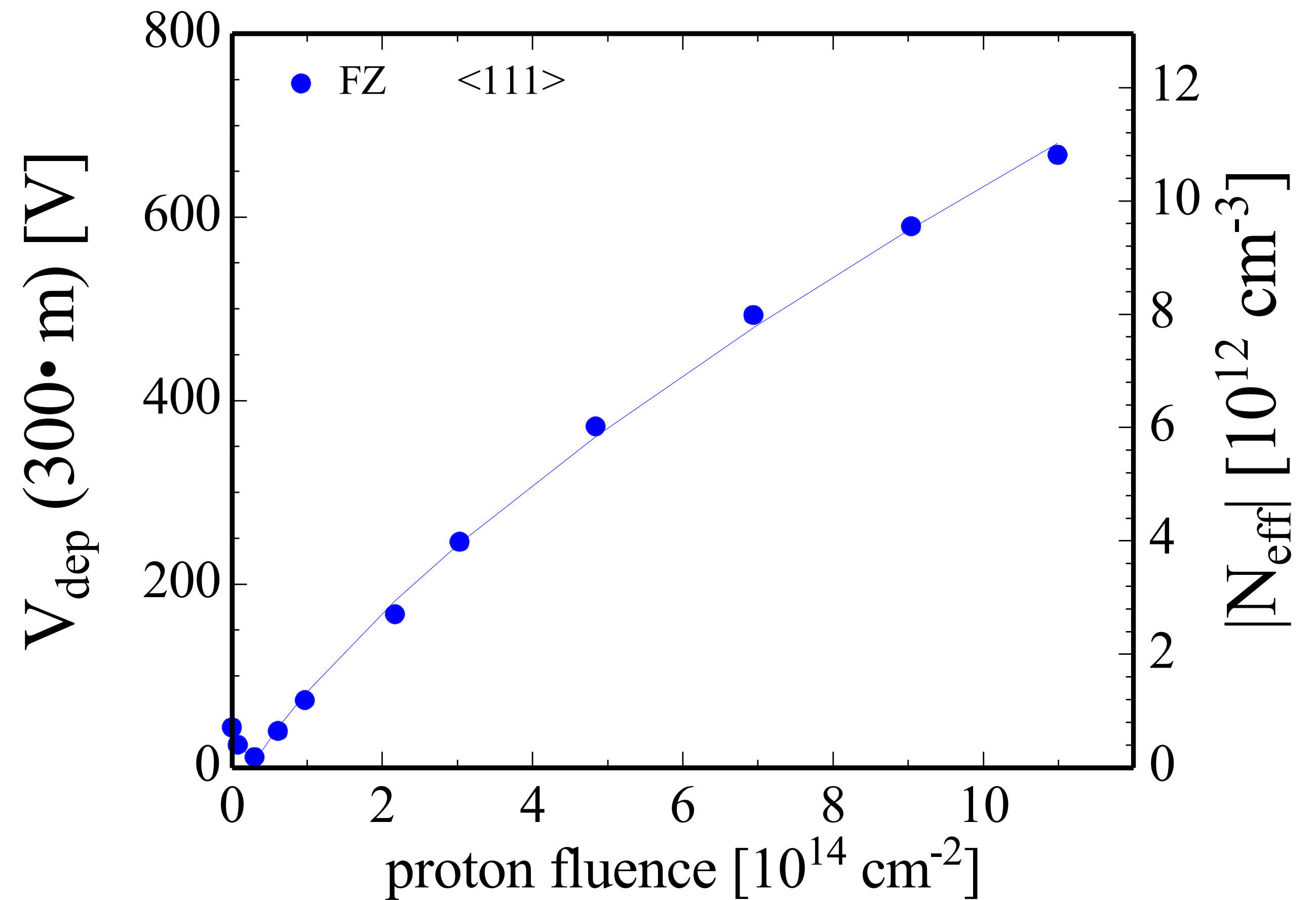
Cluster related centers

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• Standard FZ silicon

- type inversion at $\sim 2 \times 10^{13} \text{ p/cm}^2$
- strong N_{eff} increase at high fluence

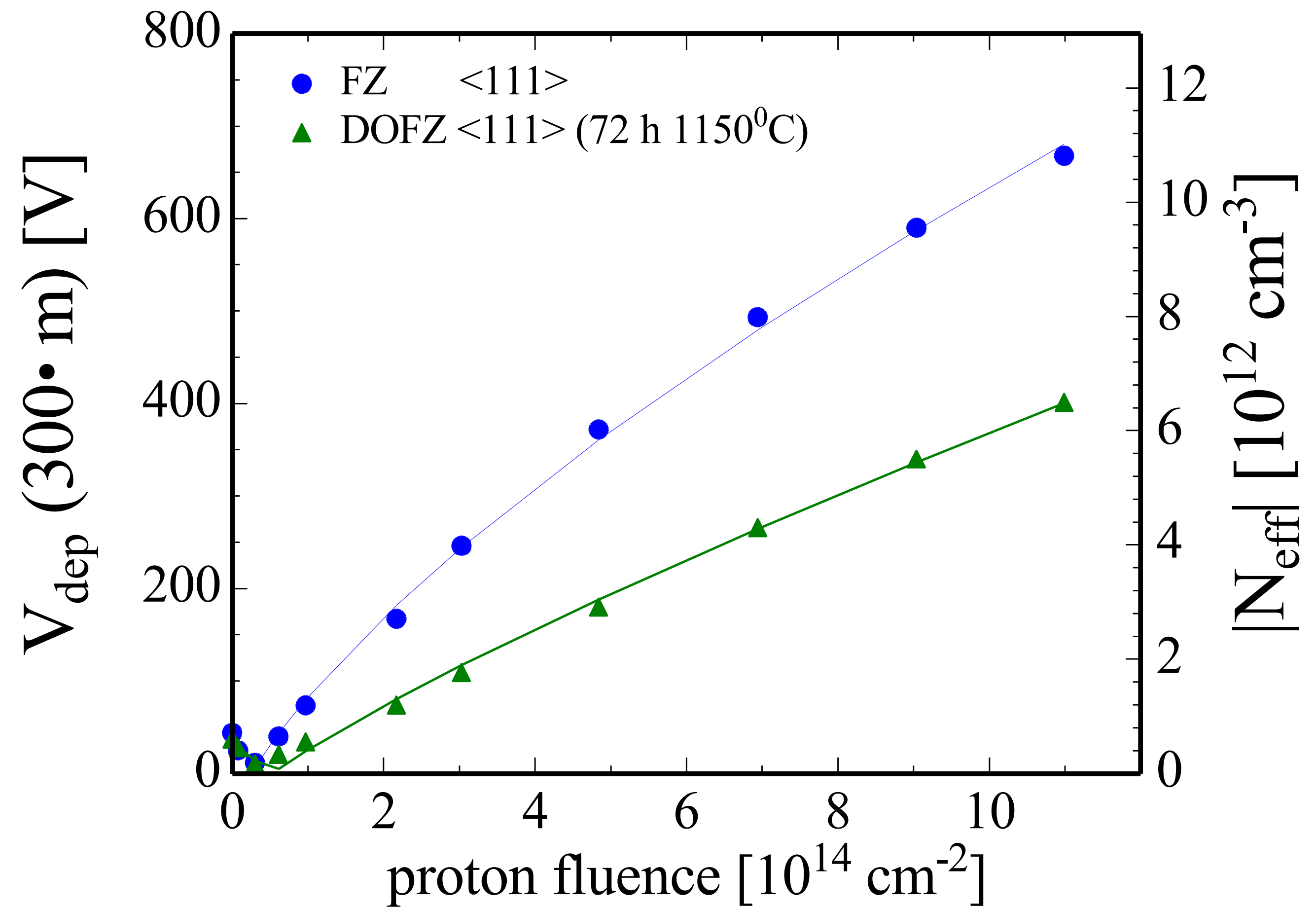


• Standard FZ silicon

- type inversion at $\sim 2 \times 10^{13} \text{ p/cm}^2$
- strong N_{eff} increase at high fluence

• Oxygenated FZ (DOFZ)

- type inversion at $\sim 2 \times 10^{13} \text{ p/cm}^2$
- reduced N_{eff} increase at high fluence



• Standard FZ silicon

- type inversion at $\sim 2 \times 10^{13}$ p/cm²
- strong N_{eff} increase at high fluence

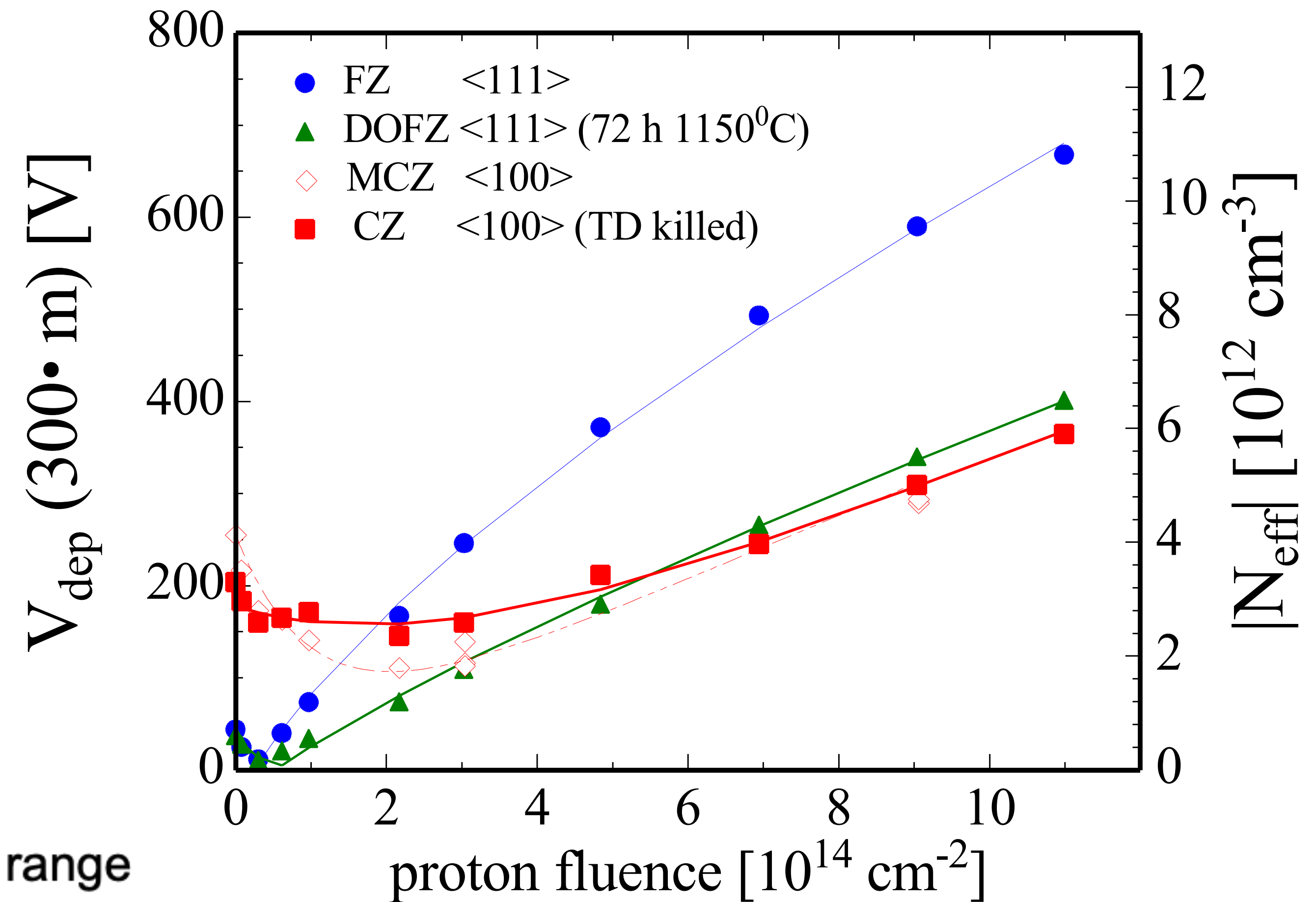
• Oxygenated FZ (DOFZ)

- type inversion at $\sim 2 \times 10^{13}$ p/cm²
- reduced N_{eff} increase at high fluence

• CZ silicon and MCZ silicon

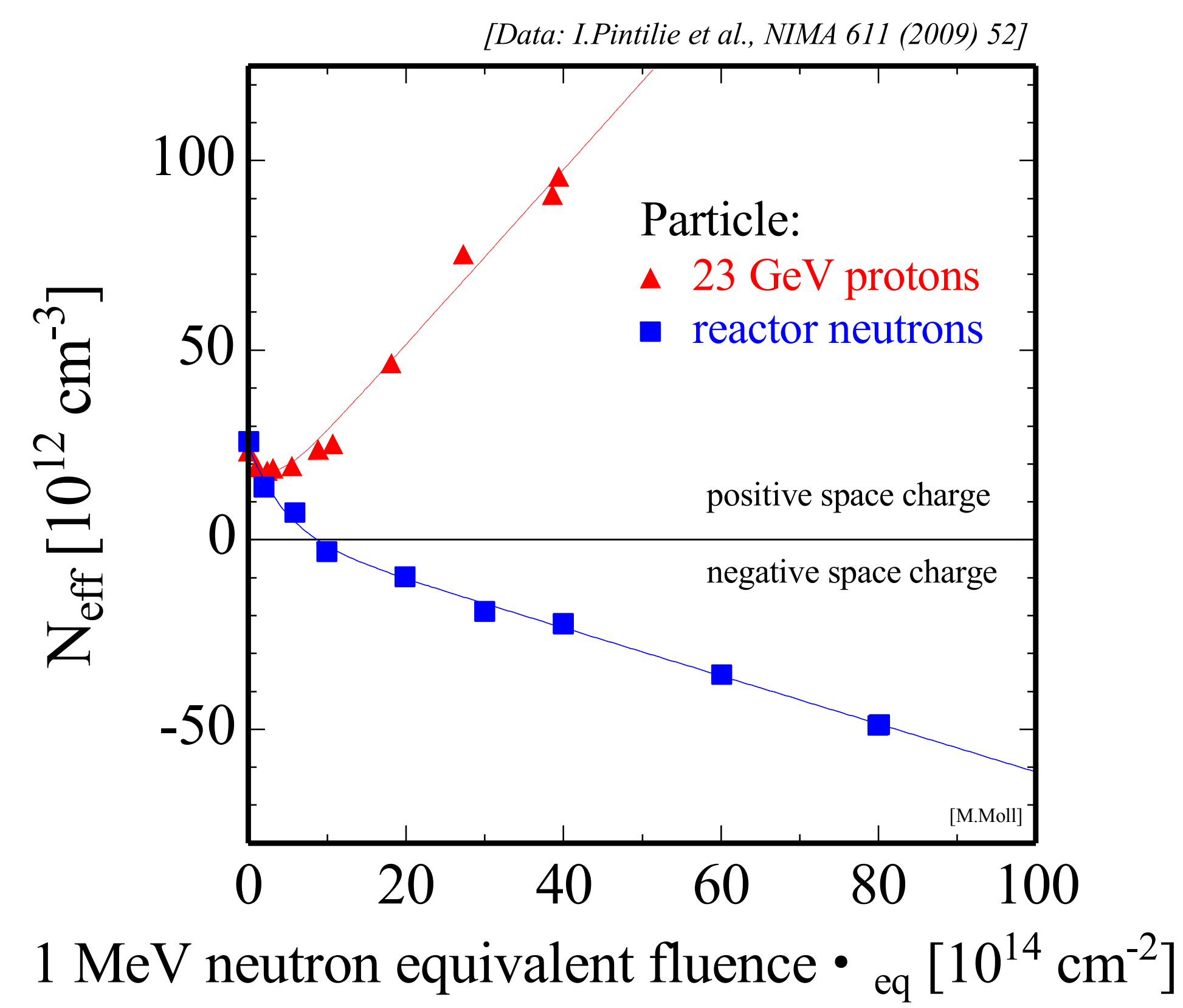
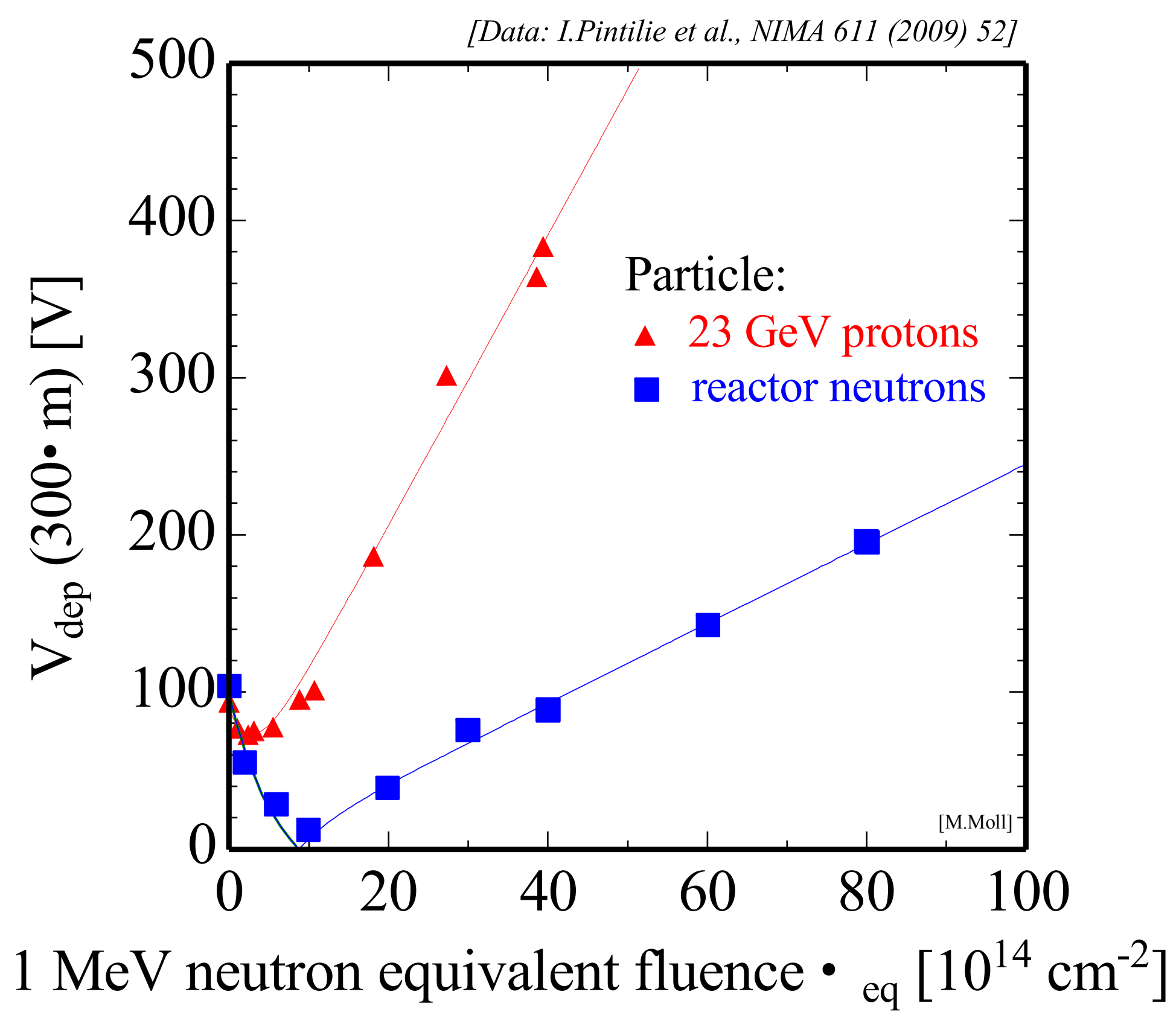
- “no type inversion” in the overall fluence range

(for experts: there is no “real” type inversion, a more clear understanding of the observed effects is obtained by investigating directly the internal electric field; look for: TCT, MCZ, double junction)





- Epitaxial silicon (*EPI-DO*, 72μm, 170Ωcm, diodes)
irradiated with **23 GeV protons** or reactor neutrons



depletion voltage $\rightarrow$

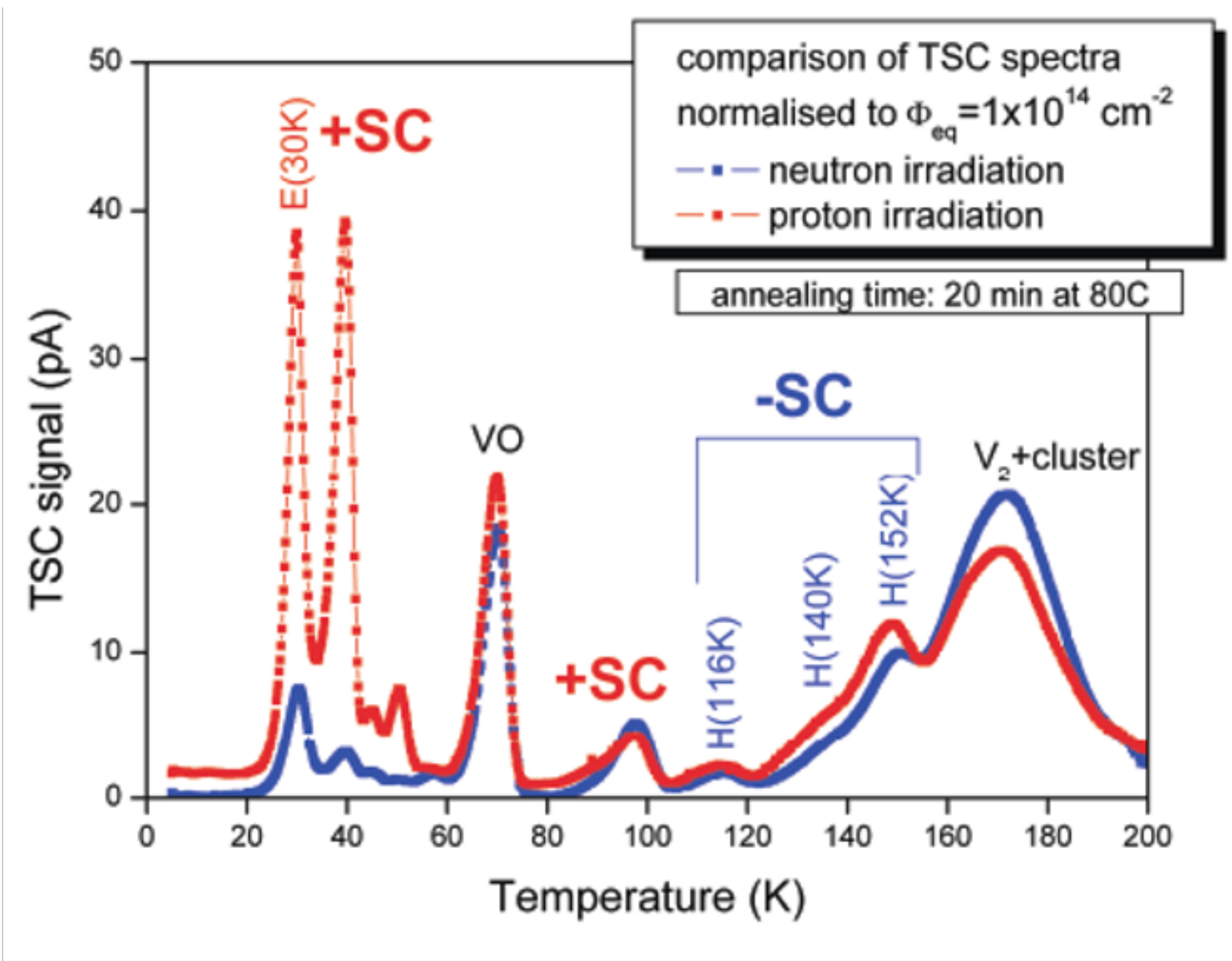
$$V_{dep} = \frac{q_0}{\epsilon \epsilon_0} \cdot |N_{eff}| \cdot d^2$$

$\leftarrow$ absolute effective space charge density

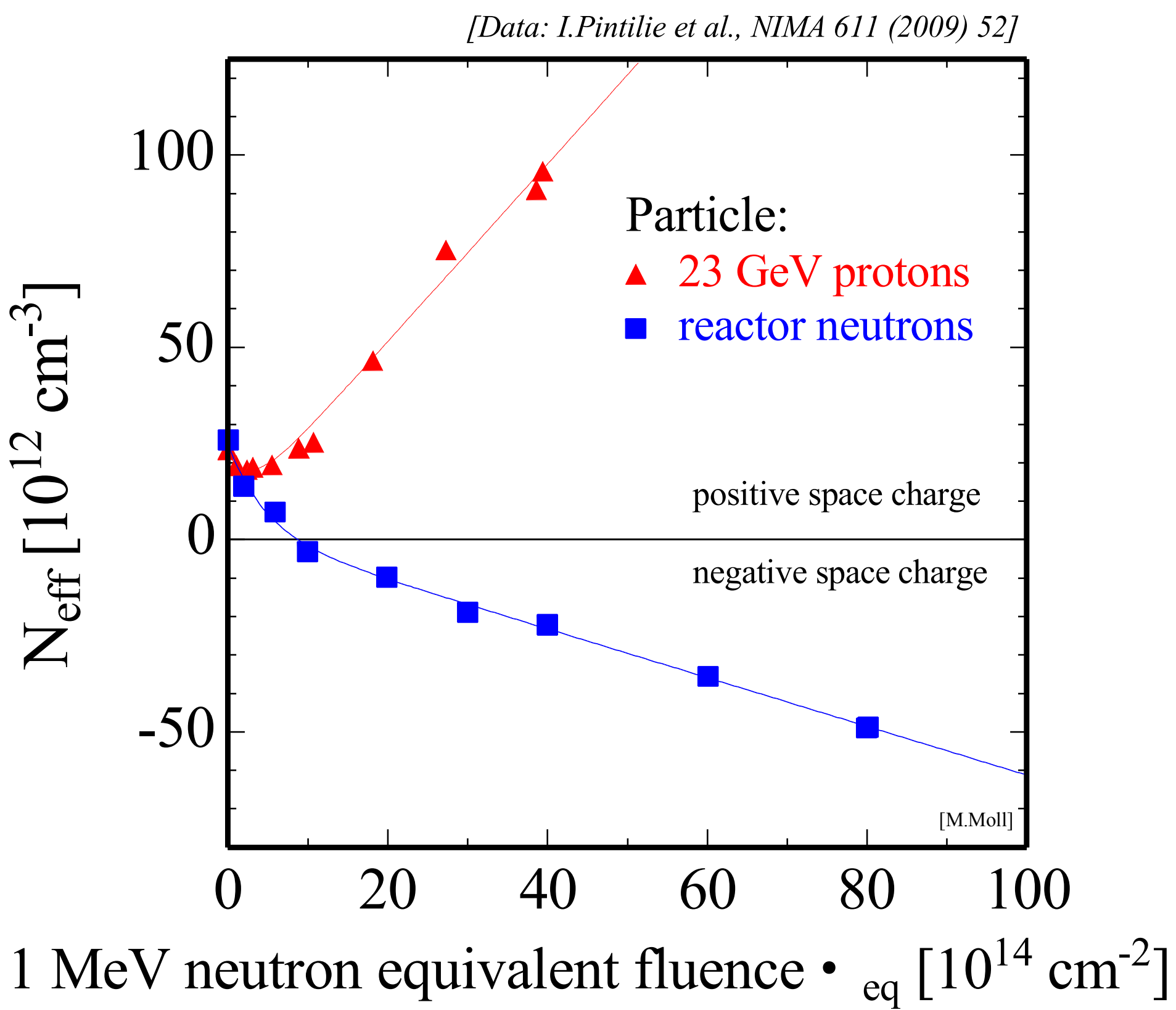
Proton vs. Neutron Irradiation



- Epitaxial silicon (*EPI-DO*, 72 μ m, 170 Ω cm, diodes)
irradiated with 23 GeV protons or reactor neutrons

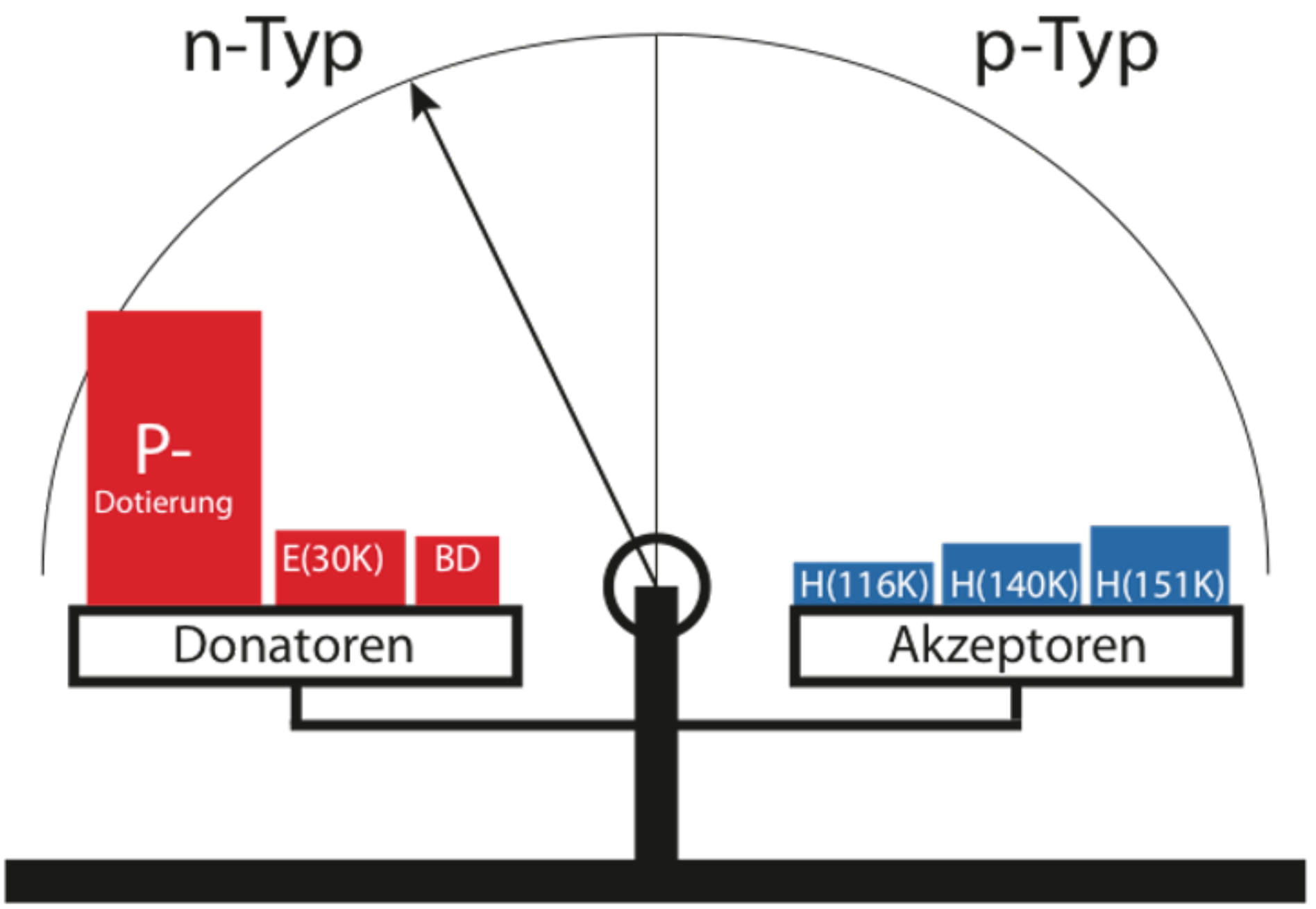
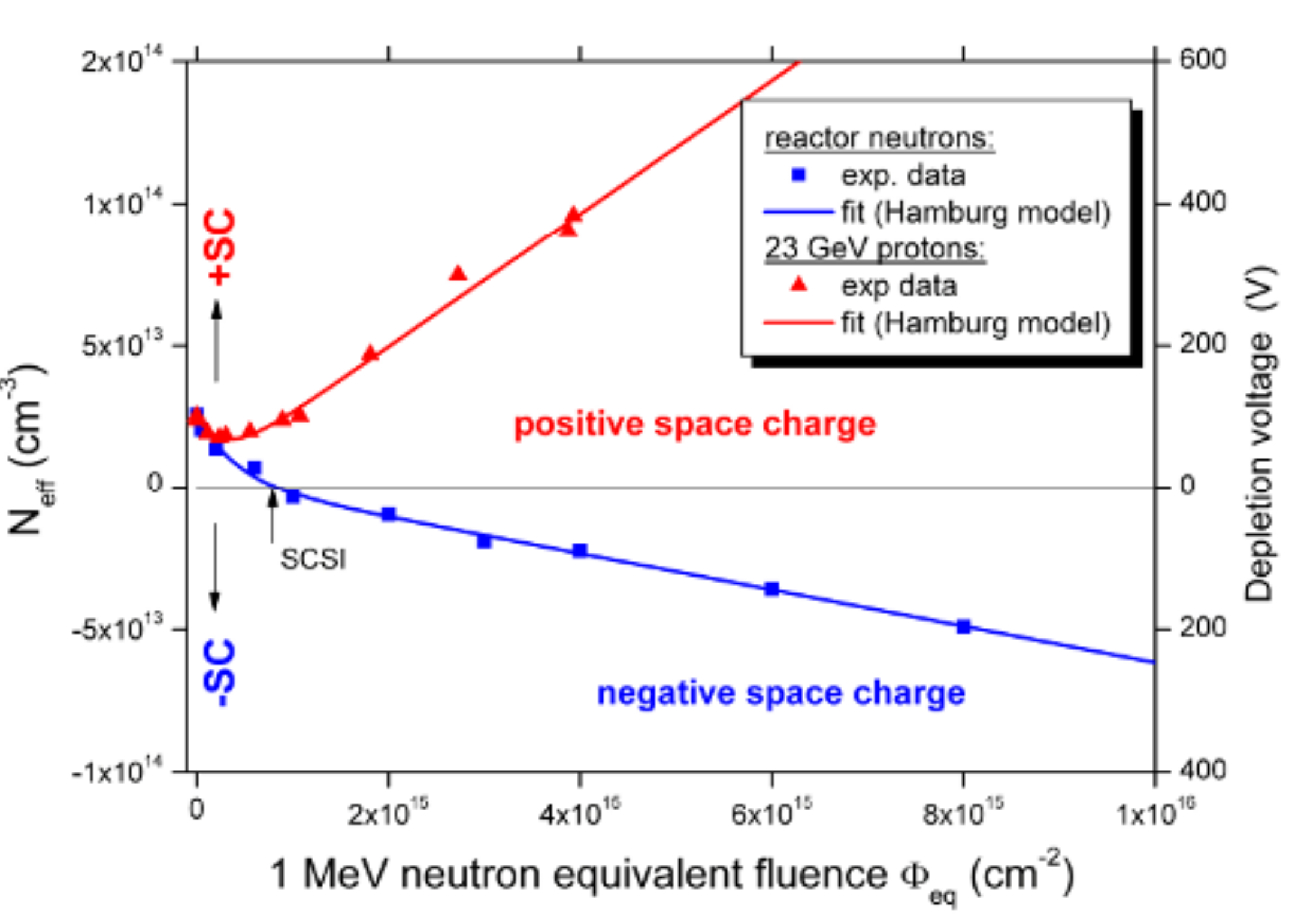


- SCSI after neutrons but not after protons
- donor generation enhanced after proton irradiation
- microscopic defects explain macroscopic effect at low Φ_{eq}

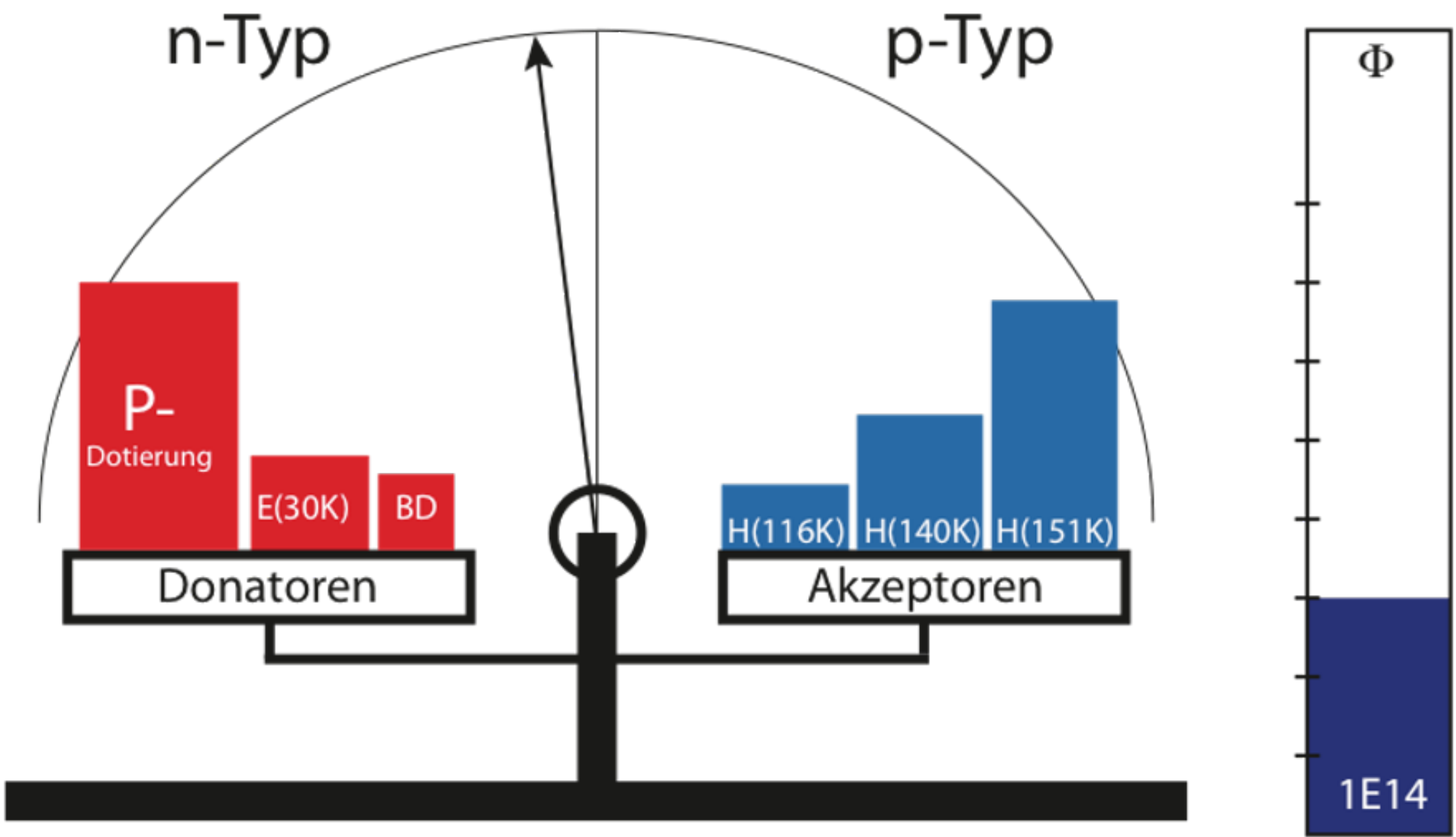
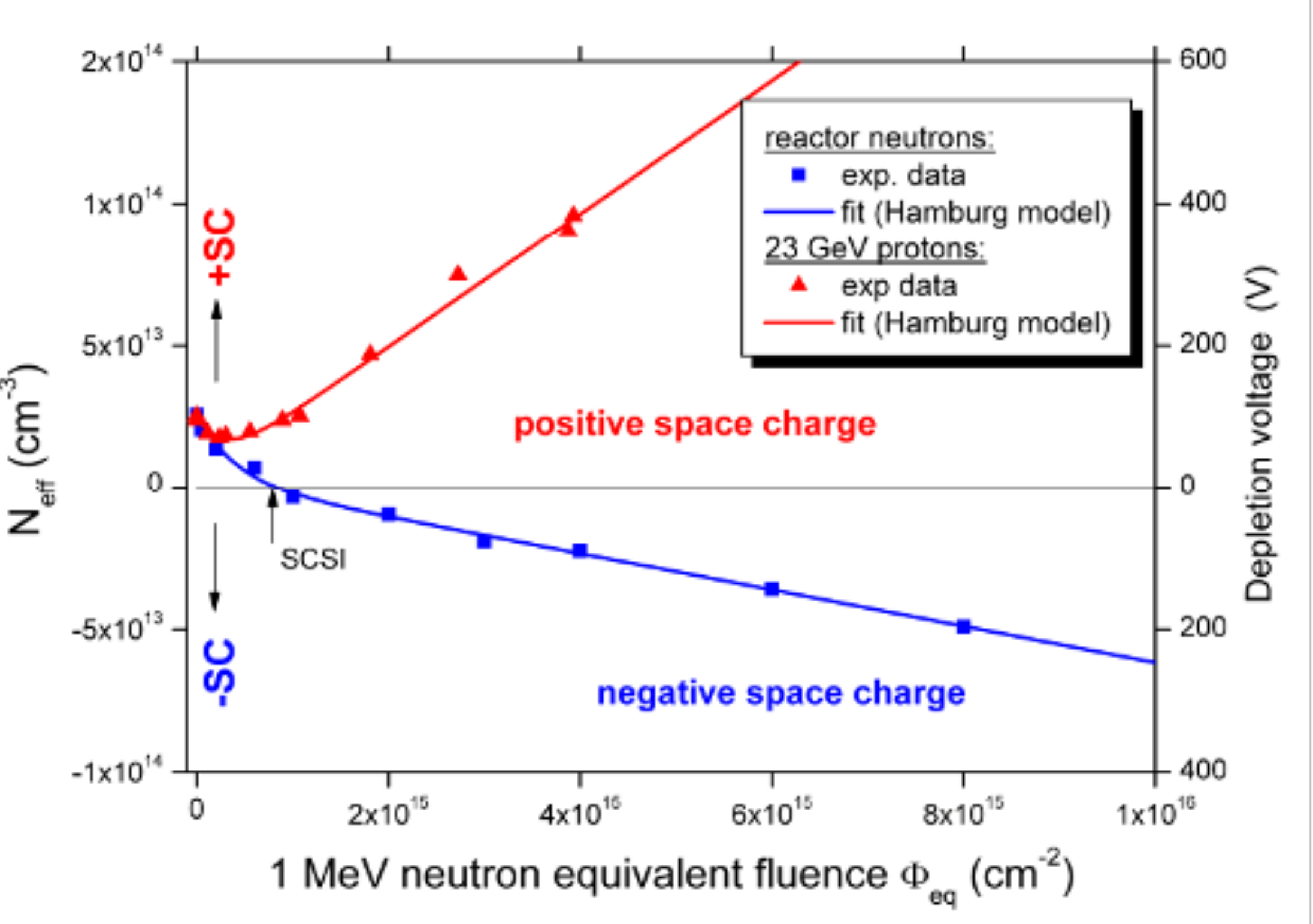


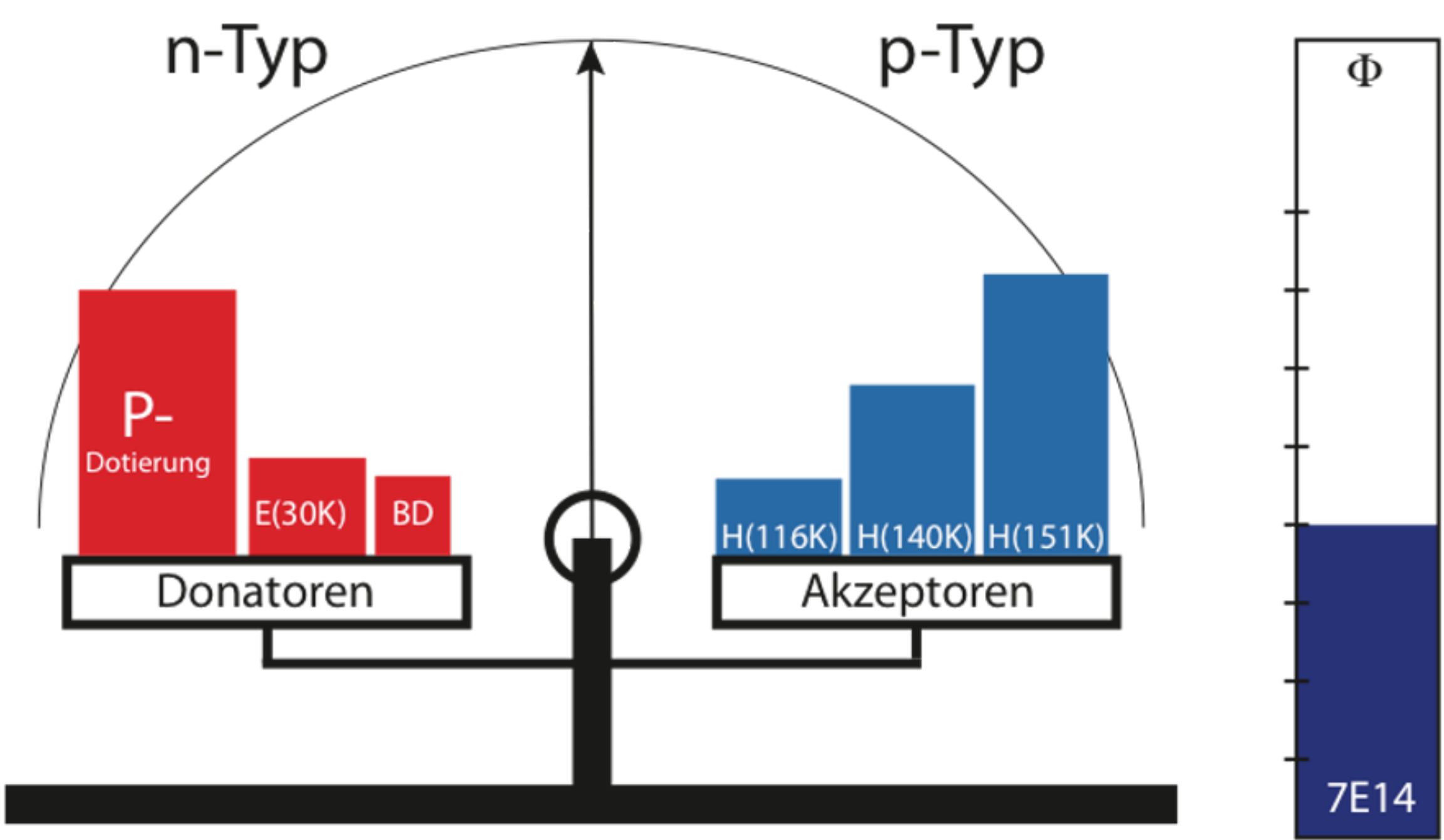
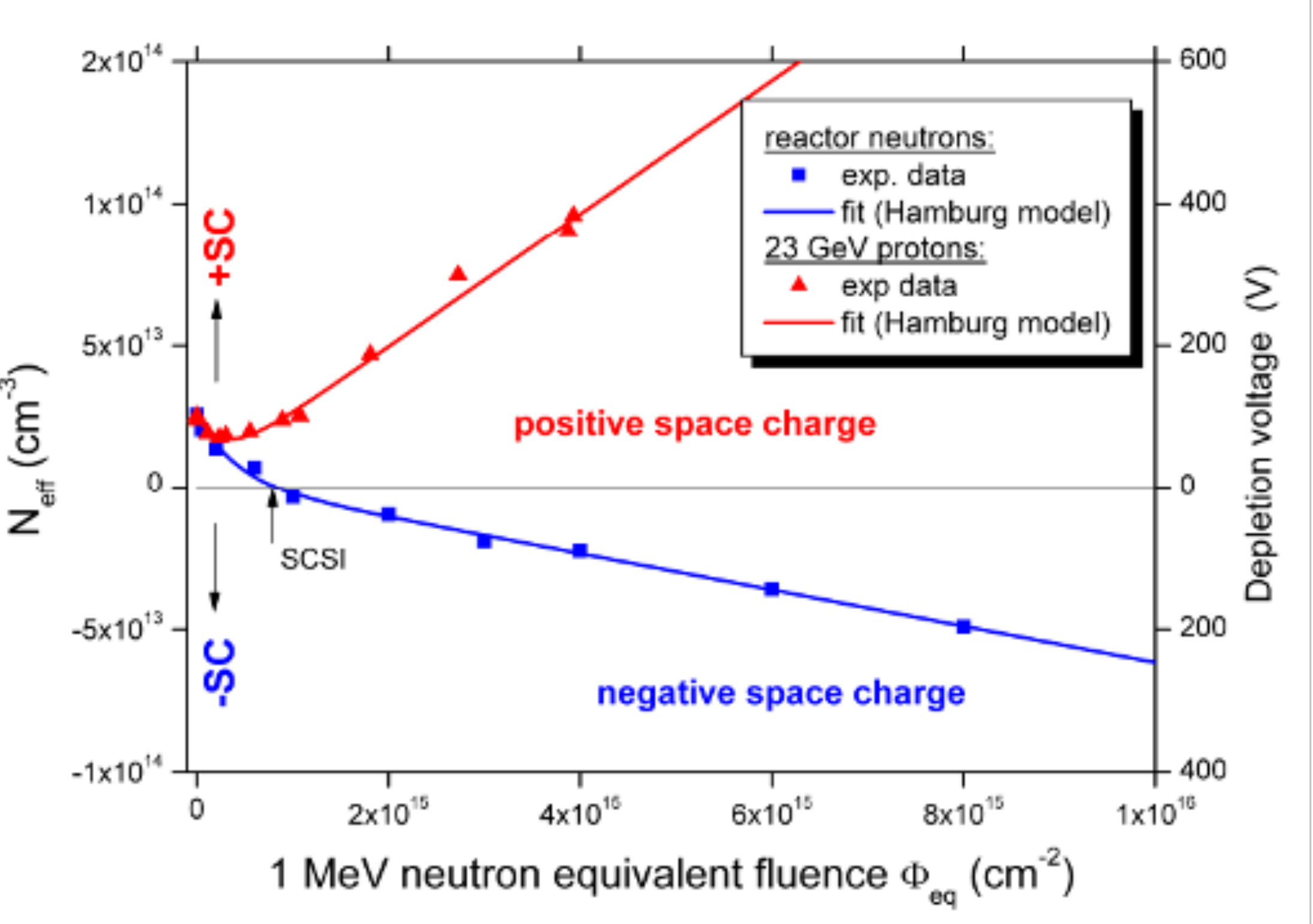


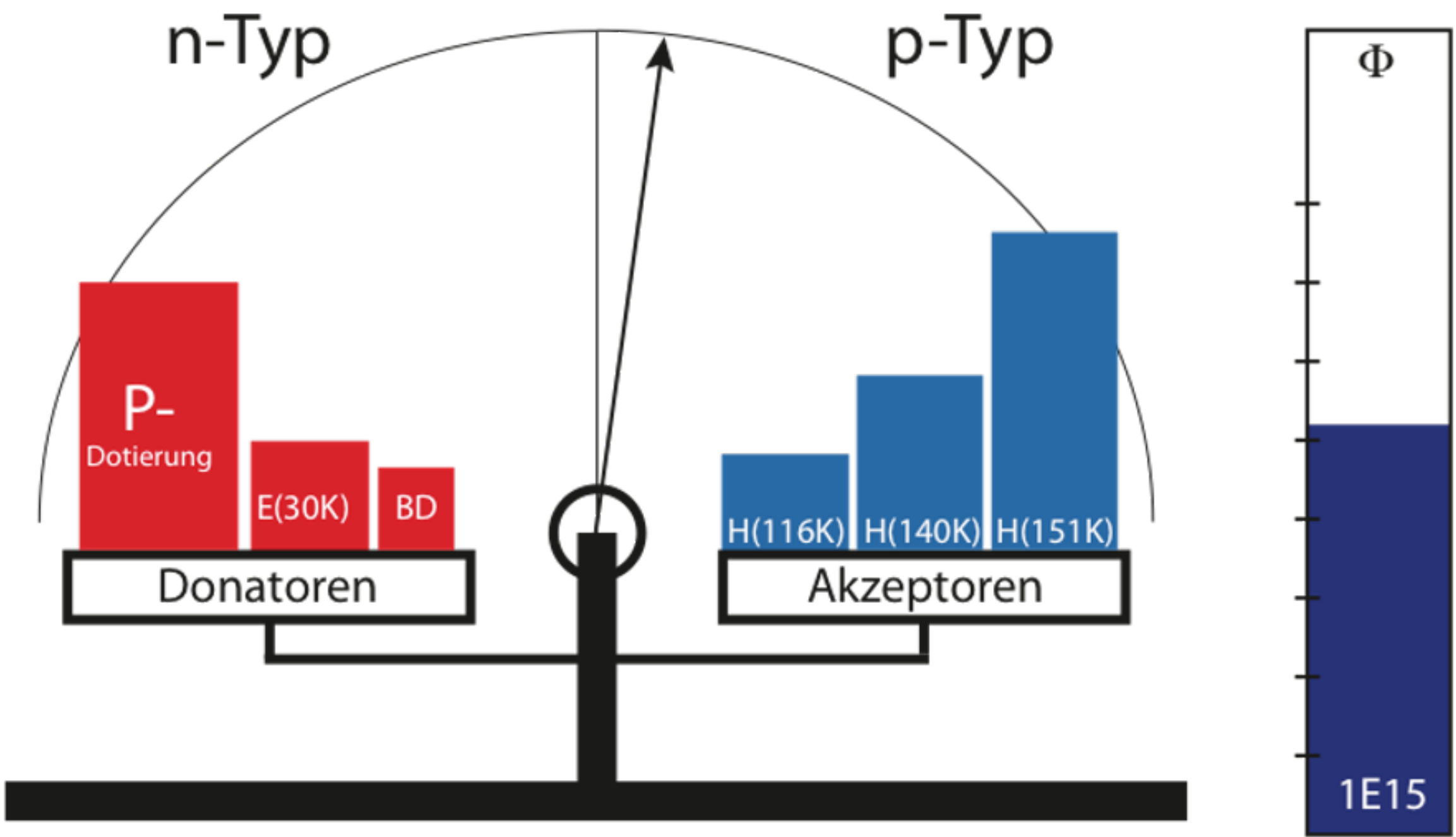
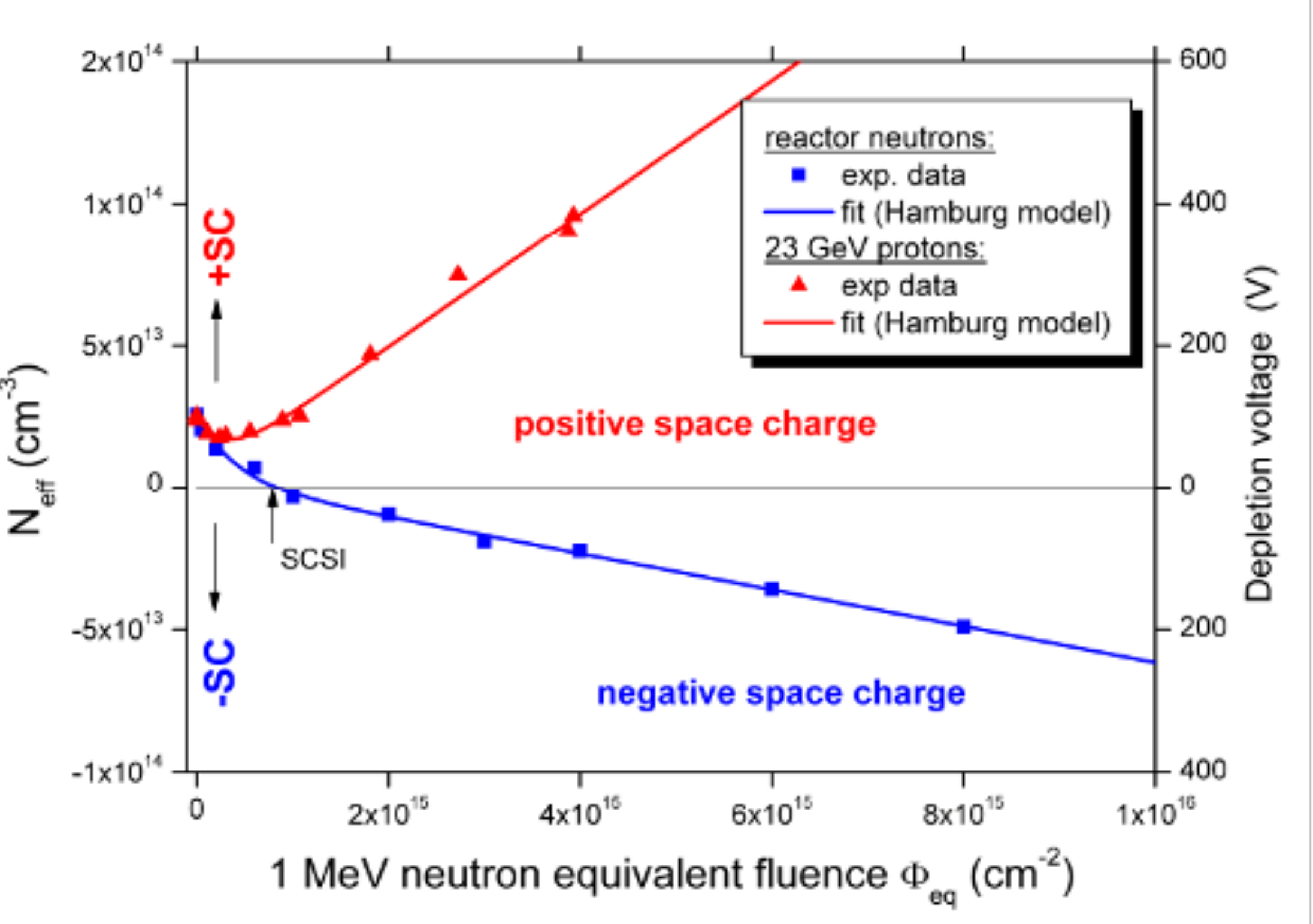
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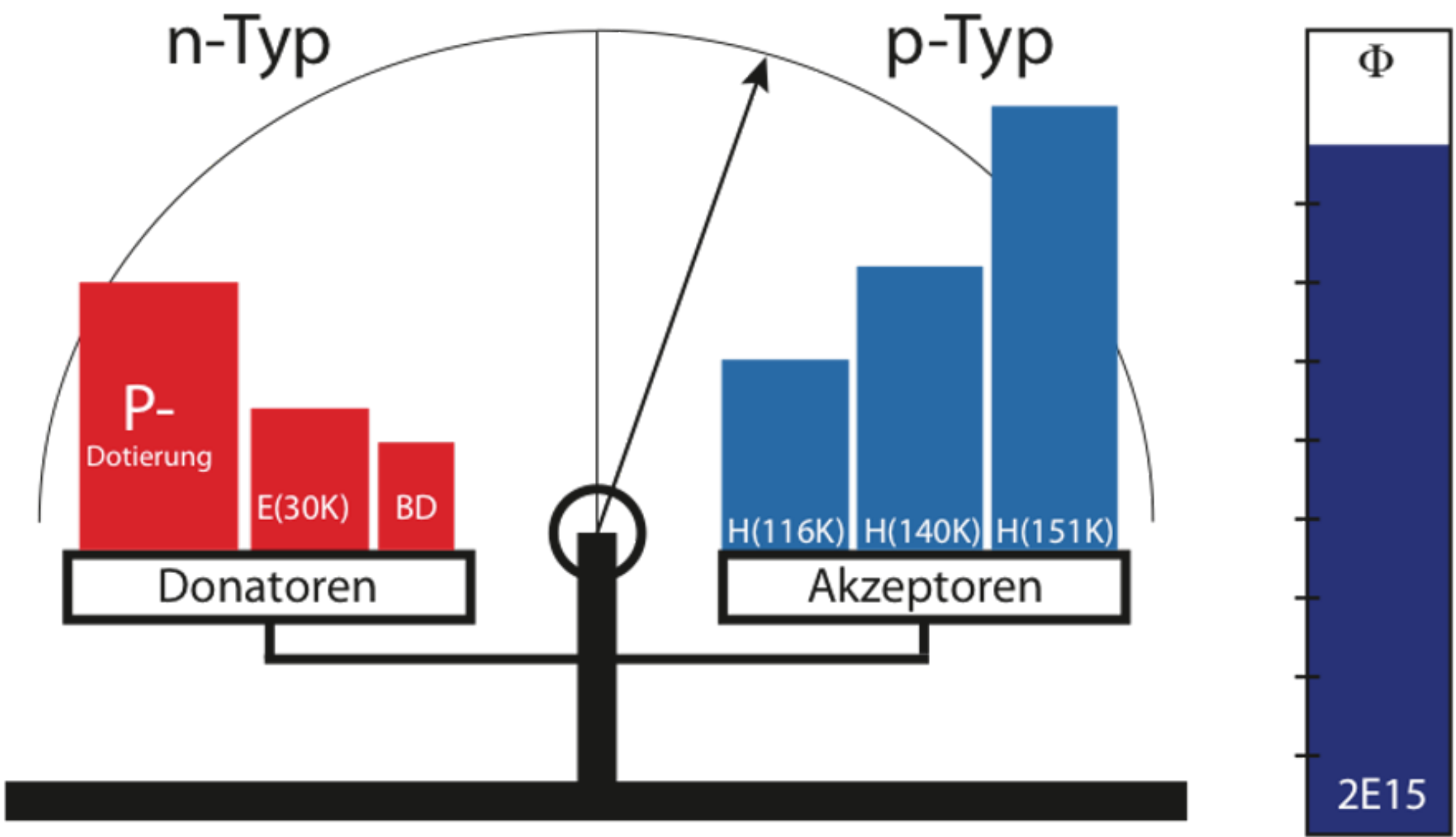
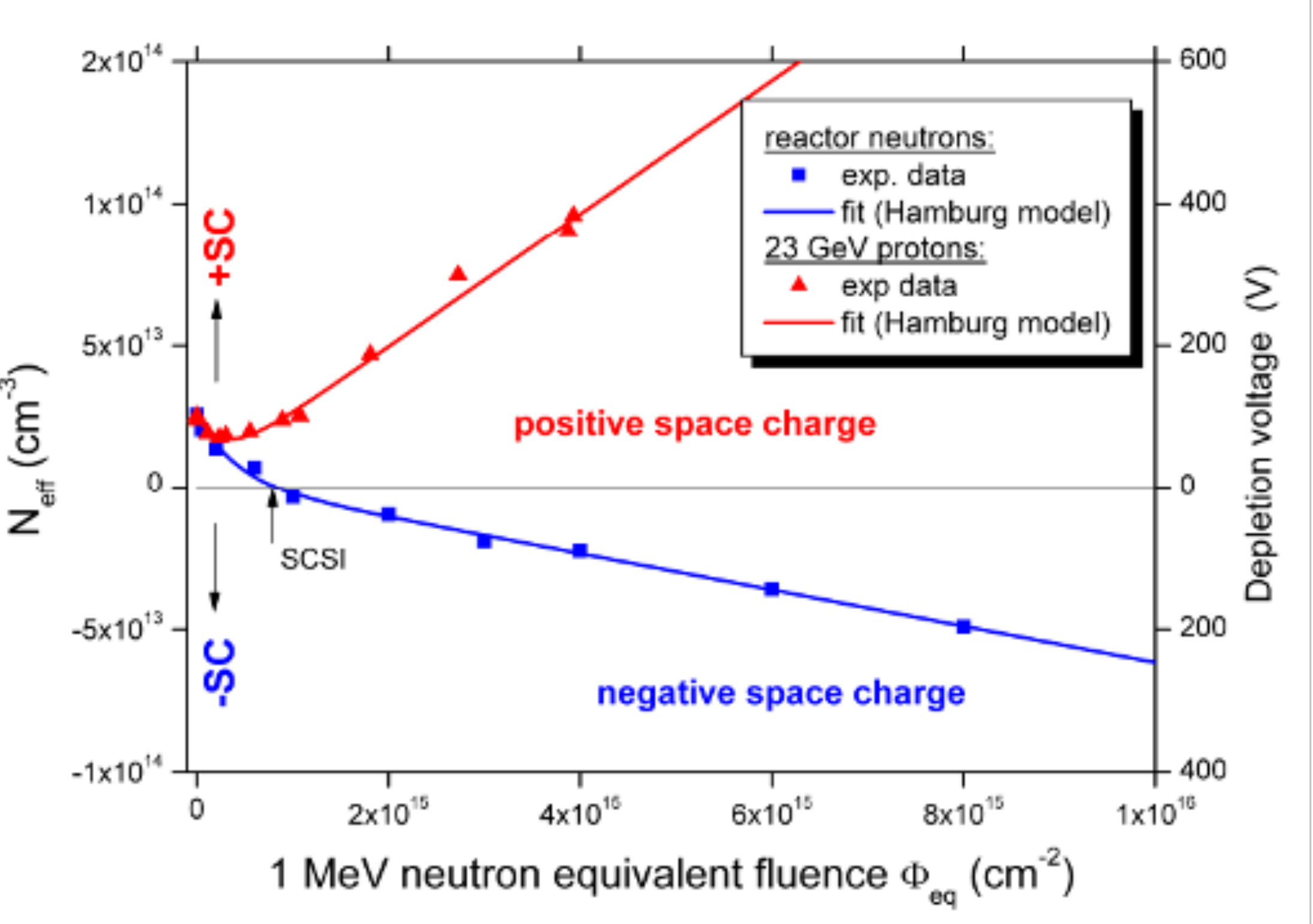


© A. Junkes



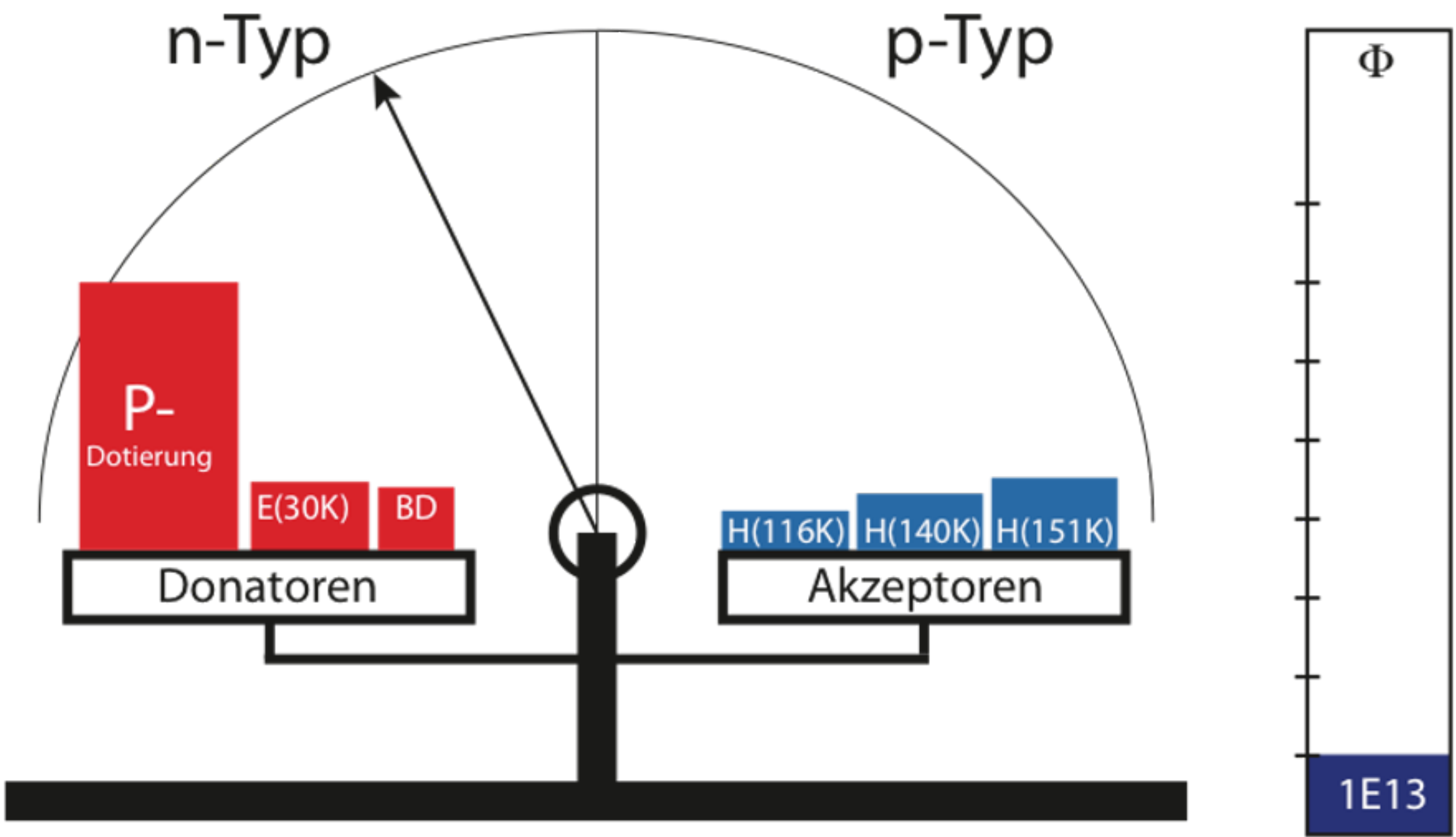
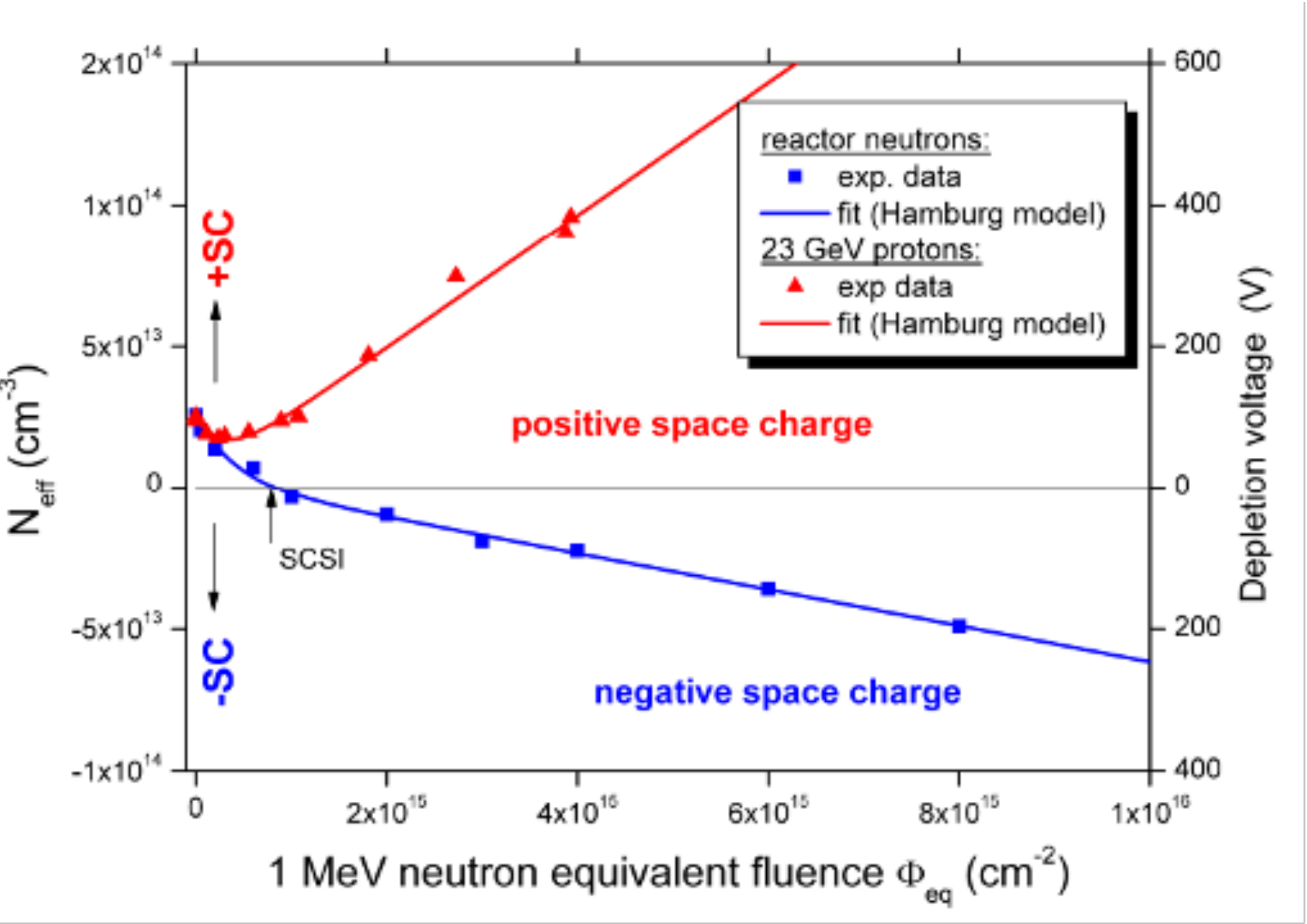


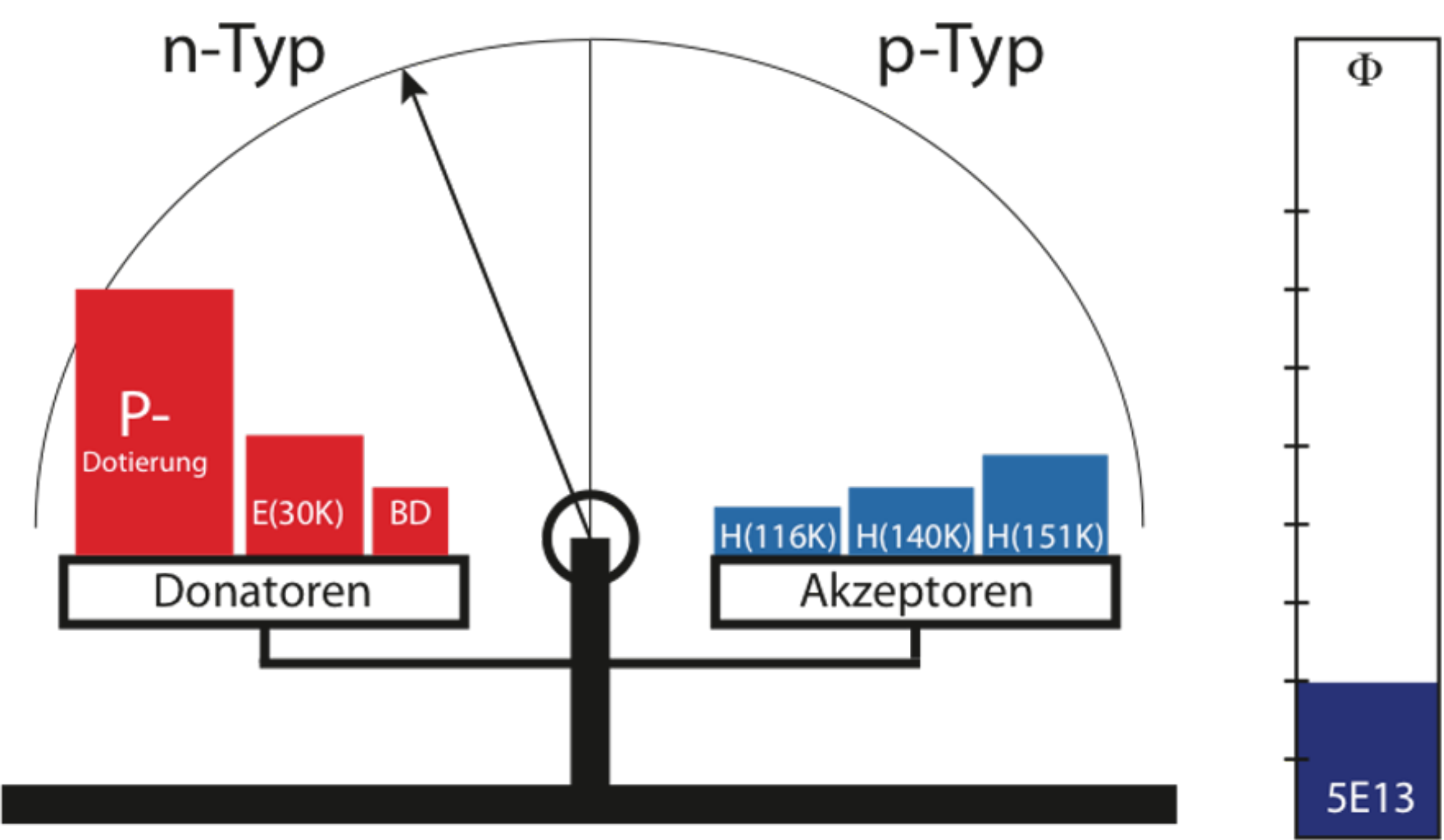
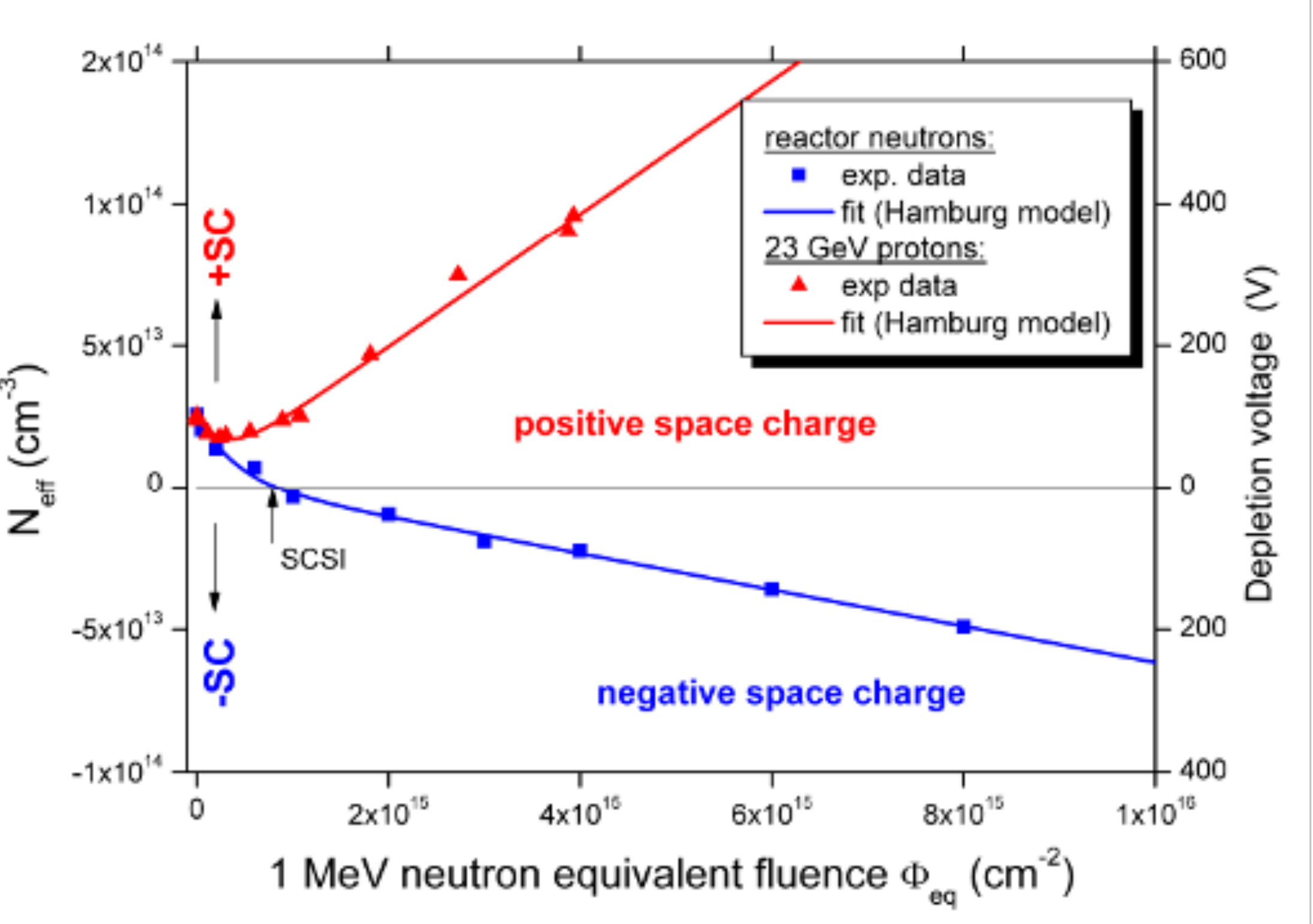


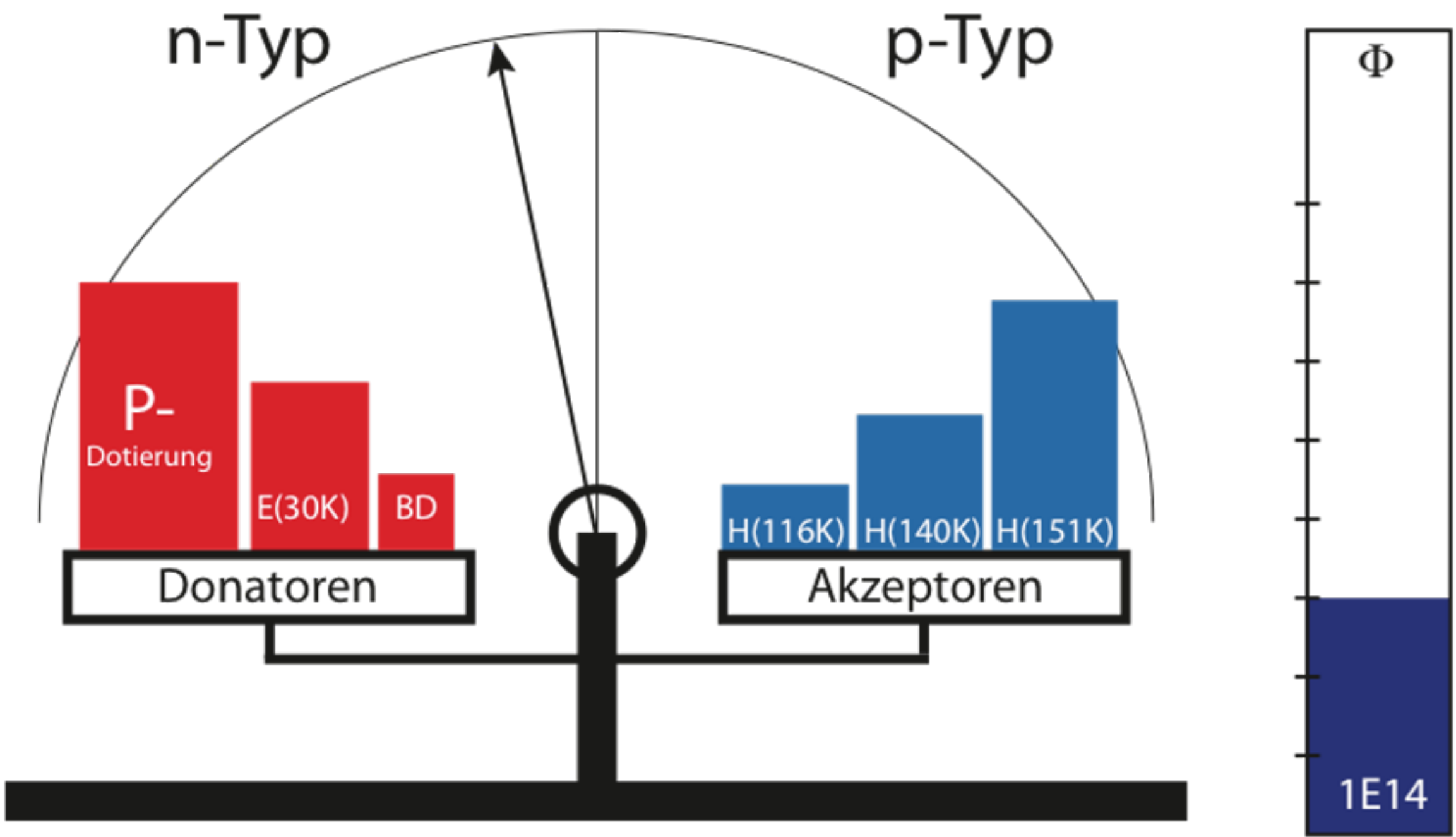
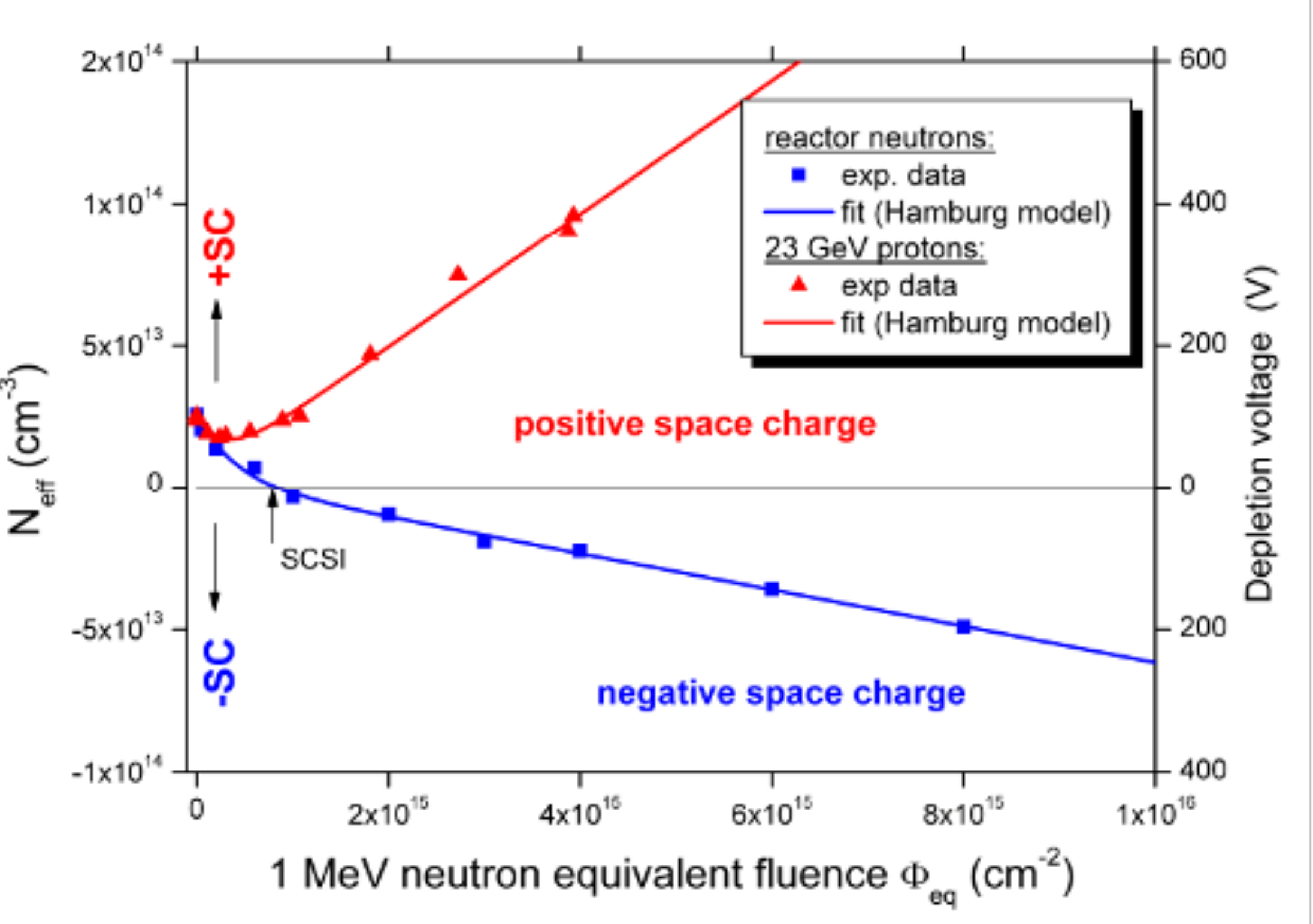


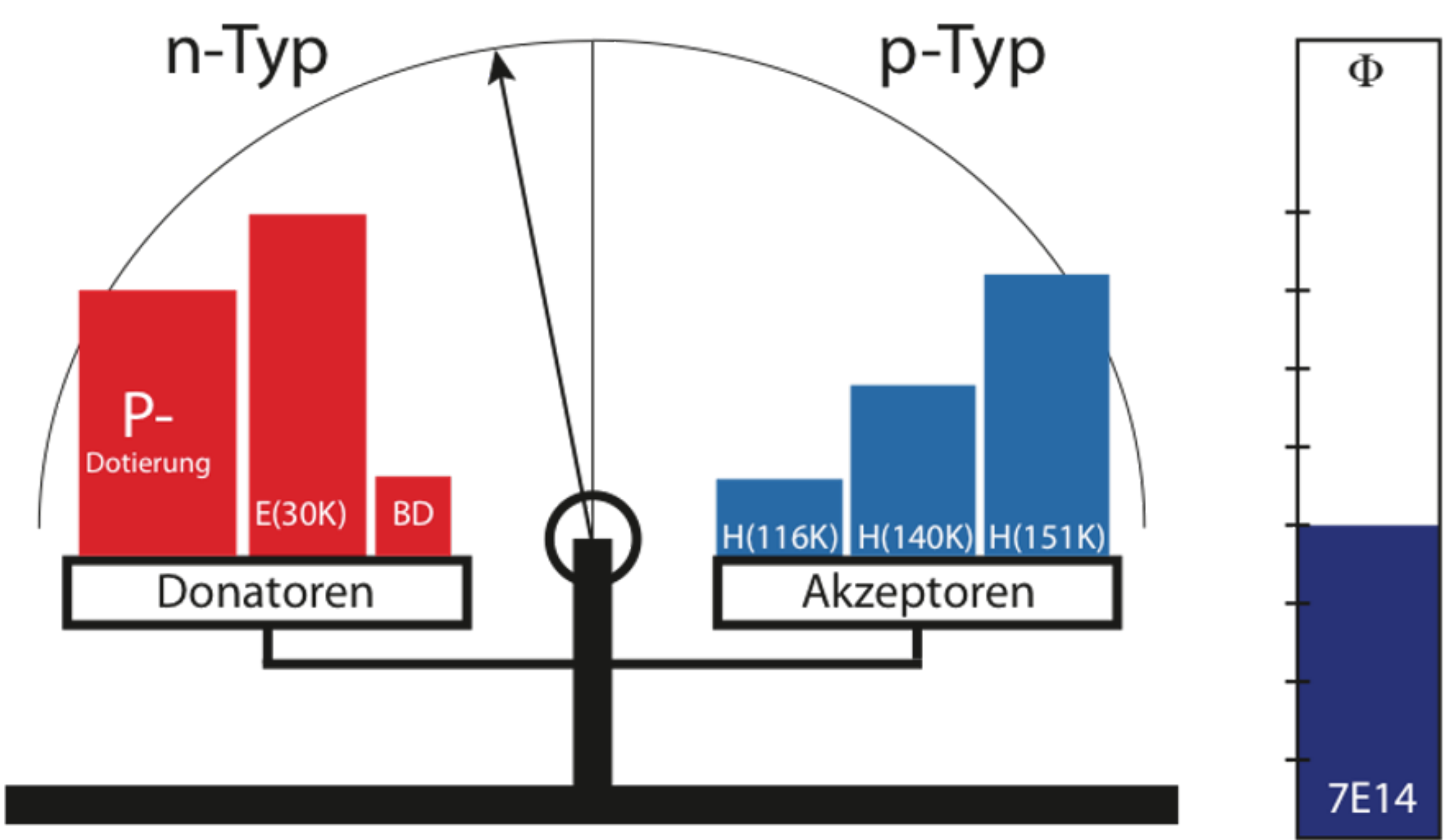
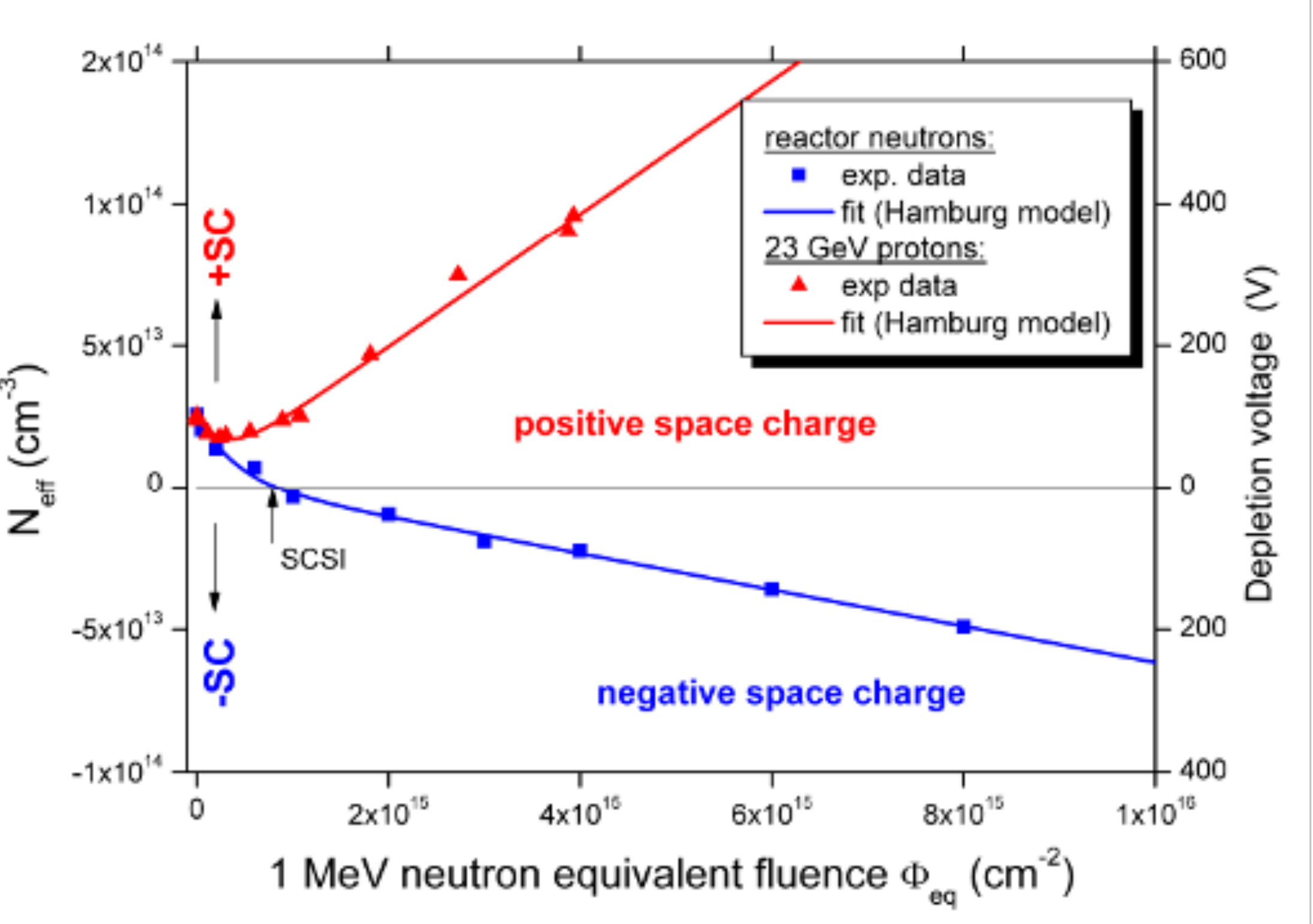


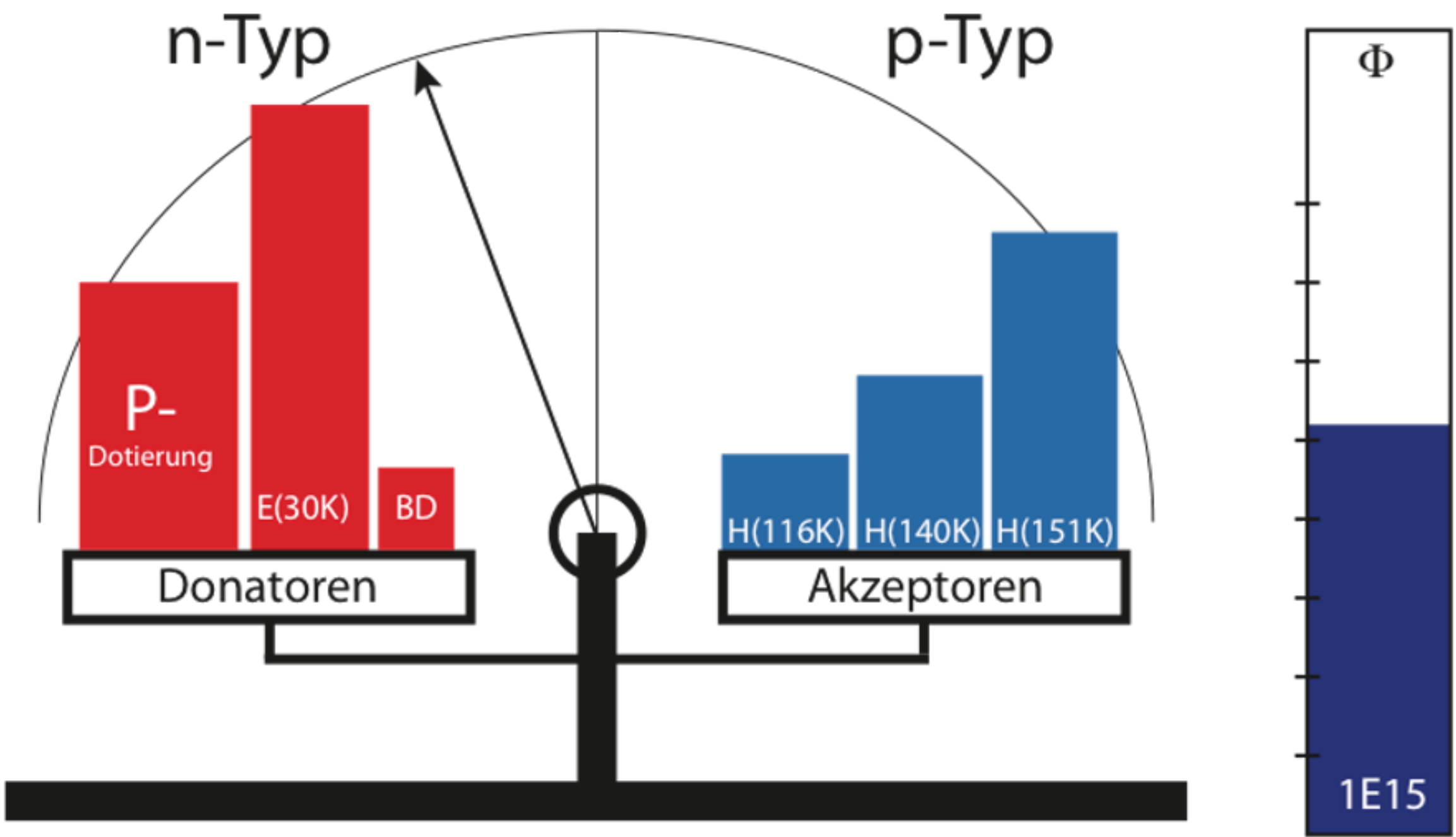
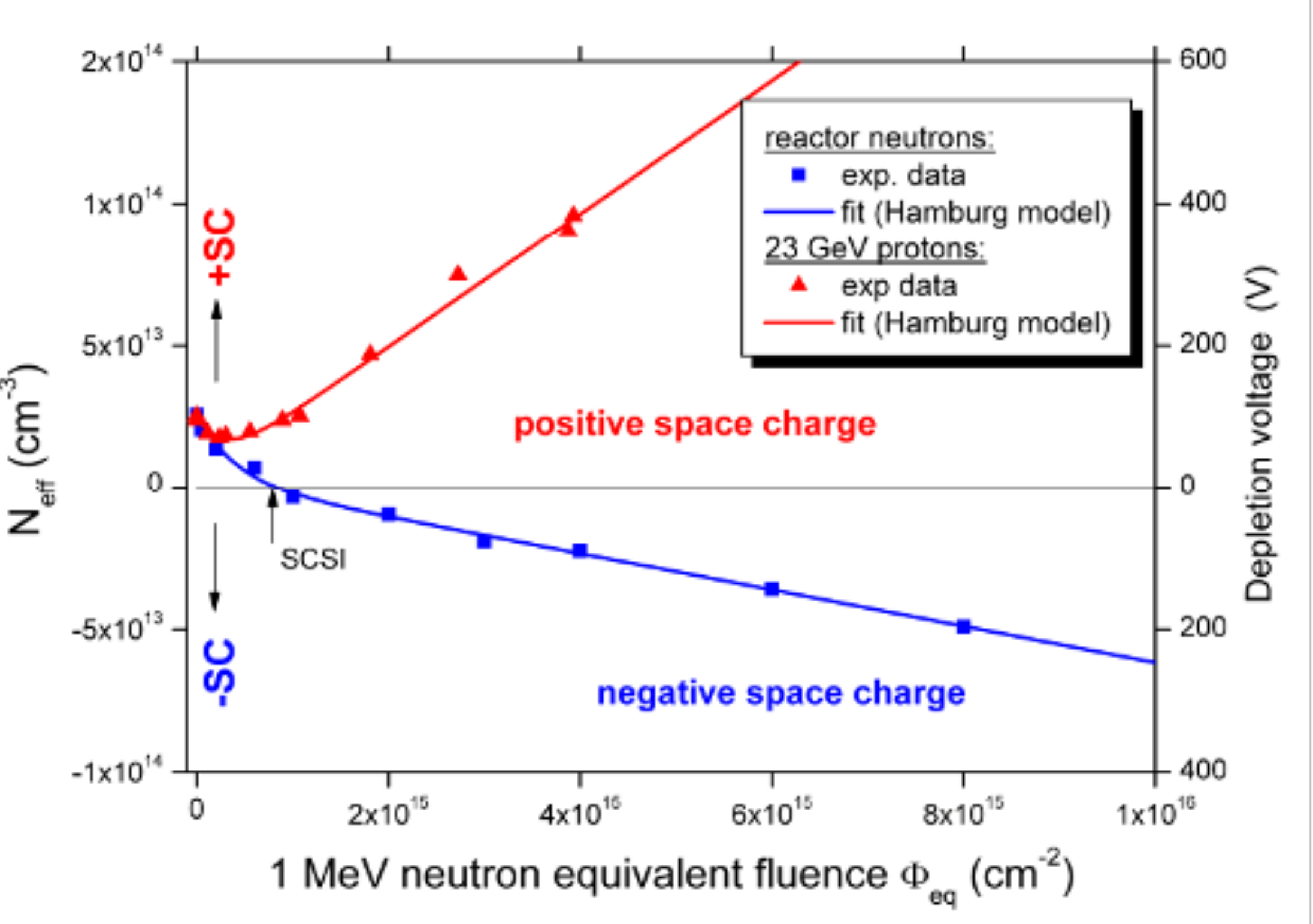
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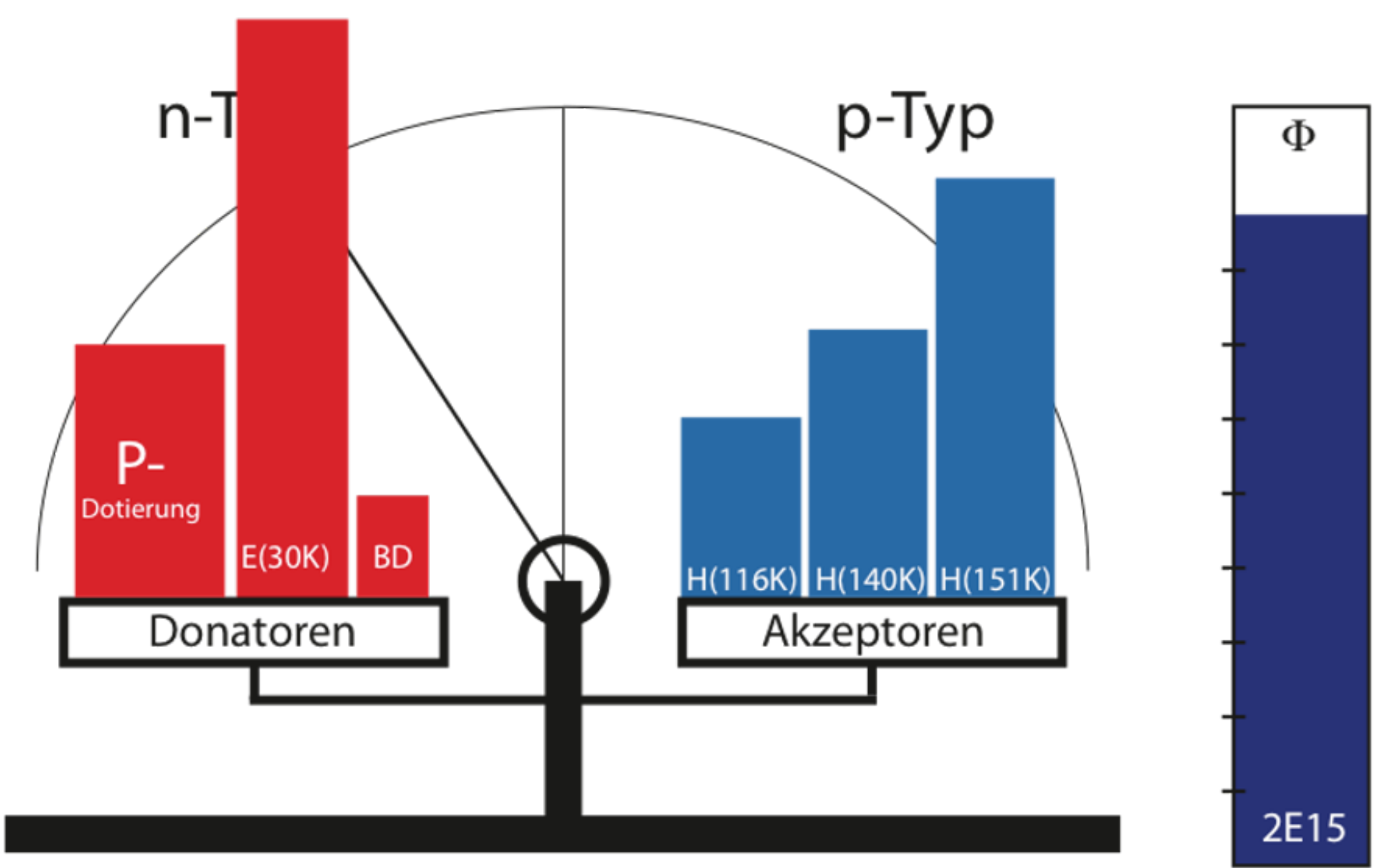
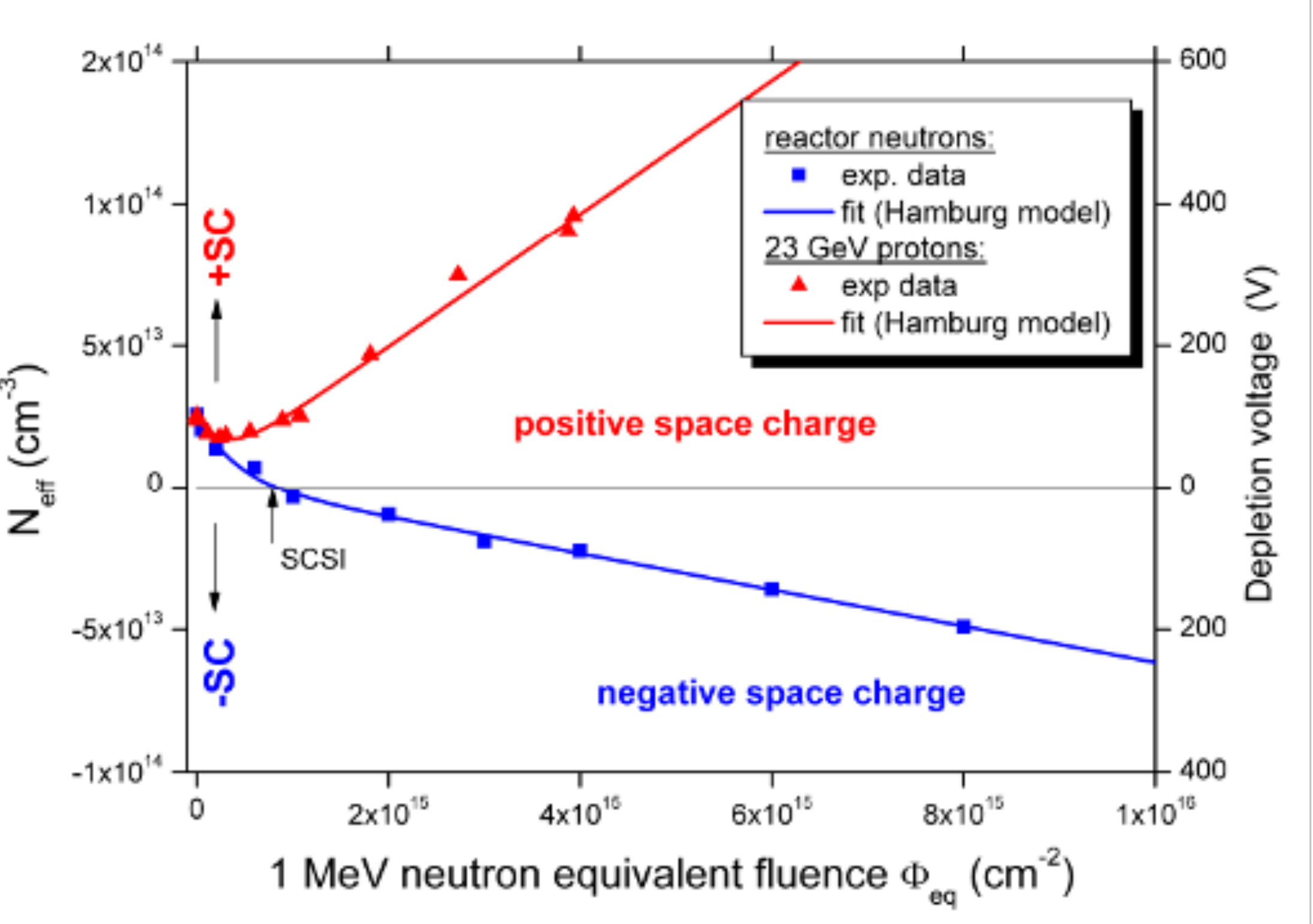














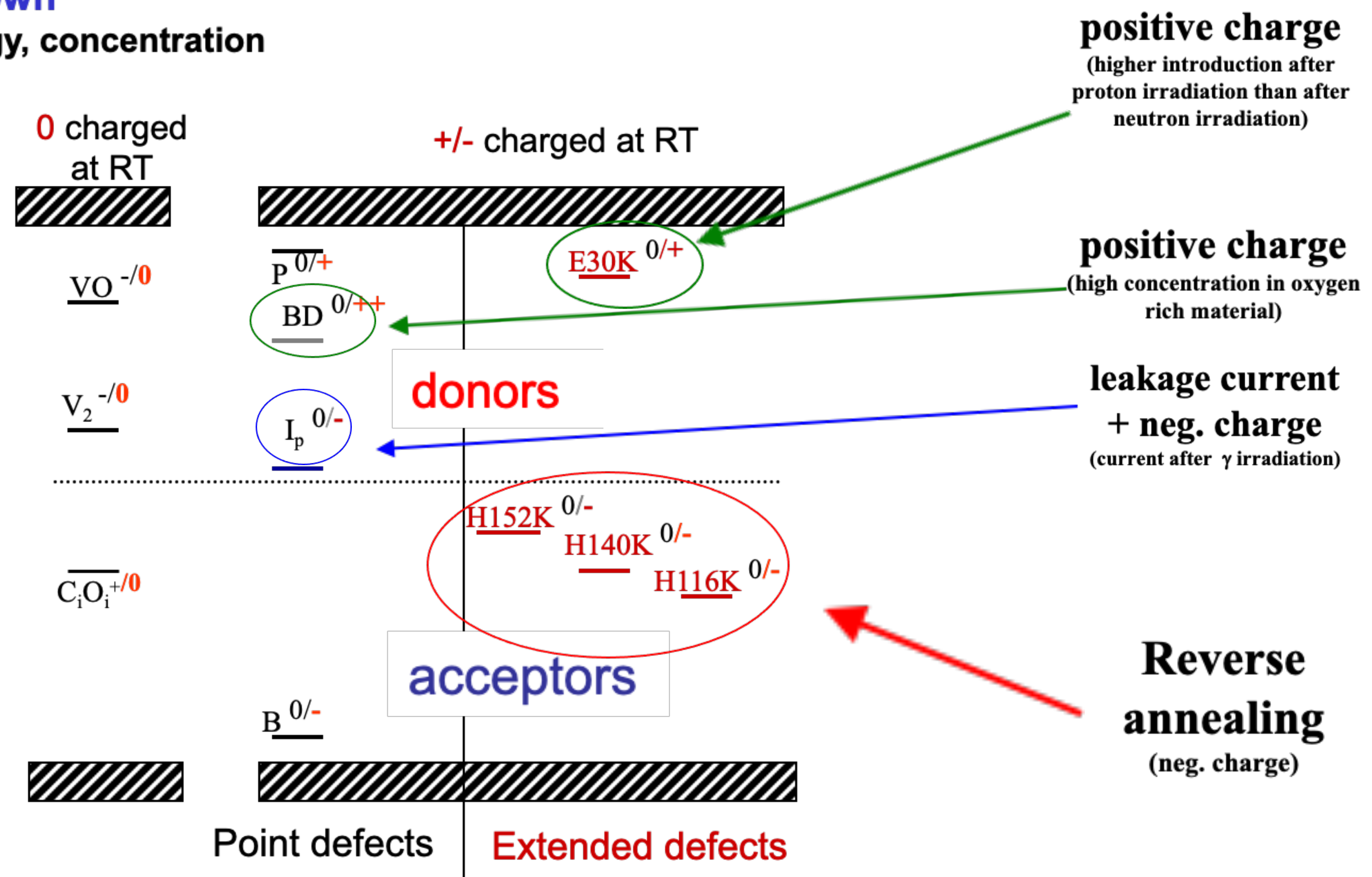
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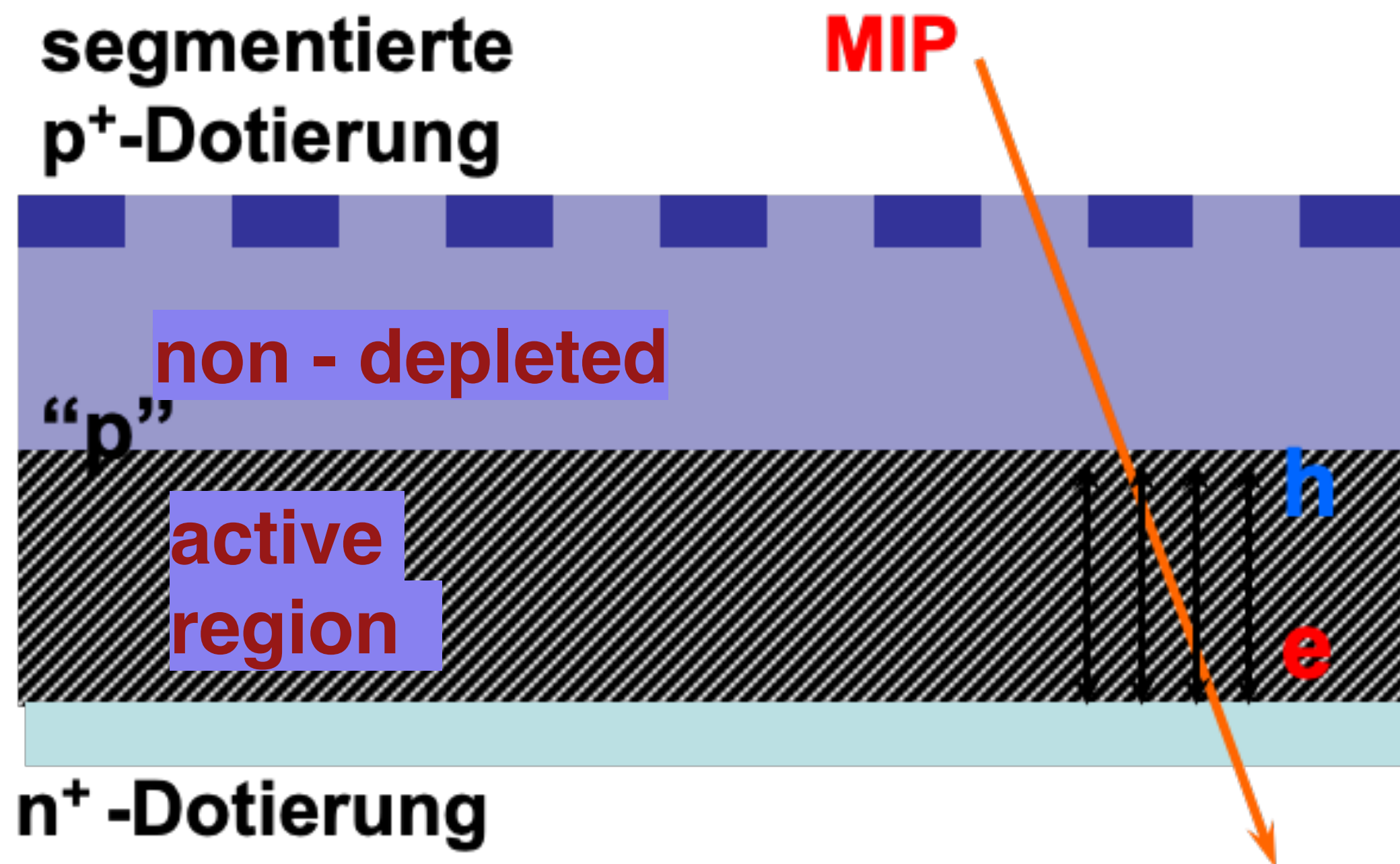


Why p-type silicon (n-in-p) for HL-LHC



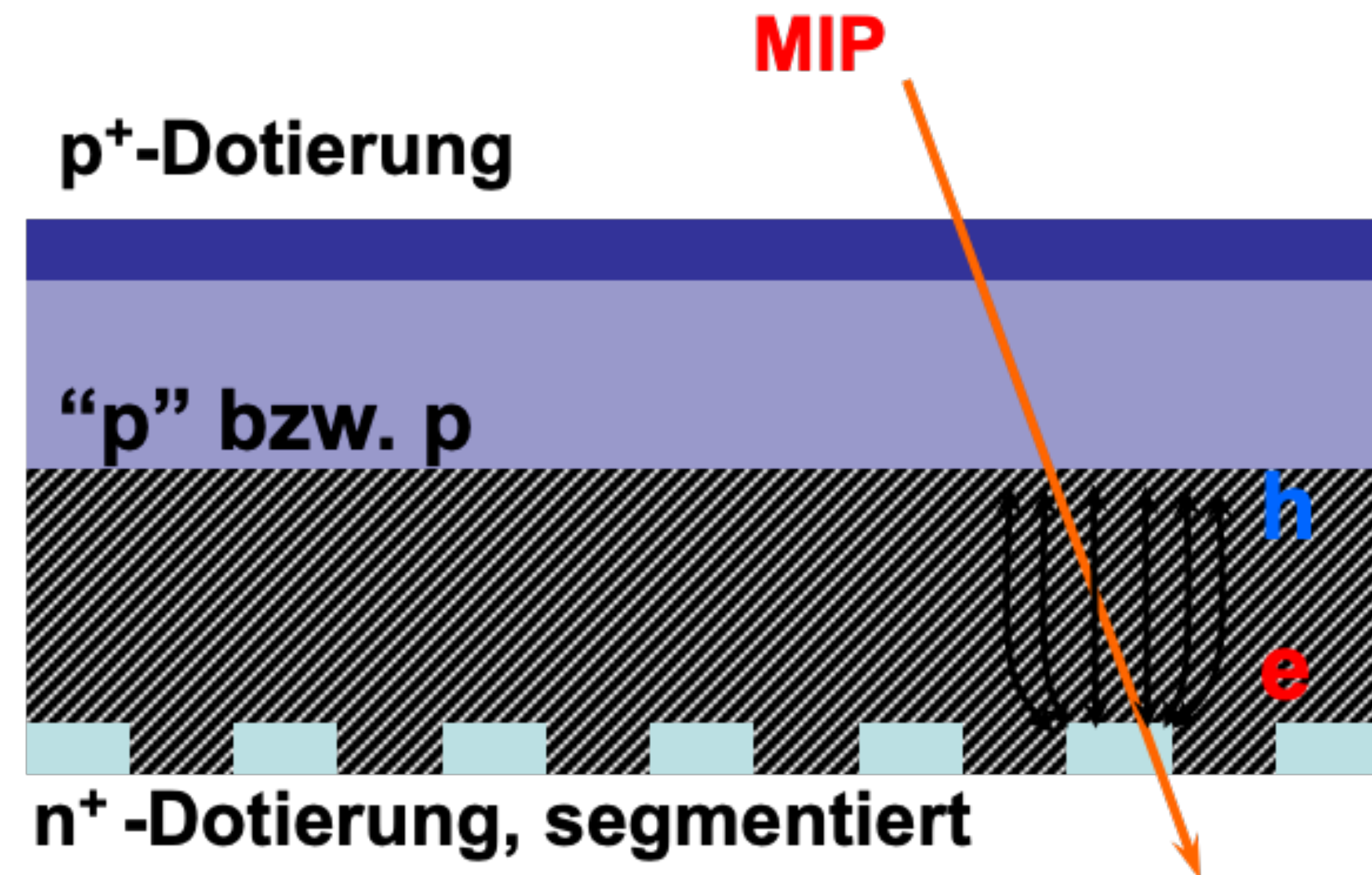
what happens in sensor after inversion:

p⁺ - in - n sensor:



- Depletion Region grows from backside
- non-depleted, i.e. isolation layer beneath front side —> lose resolution as charge not collected on electrodes
- collect holes —> trapping
- ==> overall loss of CCE and (if not depleted) resolution

n⁺ - in- n or n⁺ - in - p sensor:



- Depletion Region grows from segmented side
- non-depleted, i.e. isolation layer beneath front, non-segmented side —> lose charge but not resolution
- collect electrons —> far less trapping
- ==> smaller loss of CCE



This is not an up-to-date status of radiation damage status

There are people which to-day work on these topics

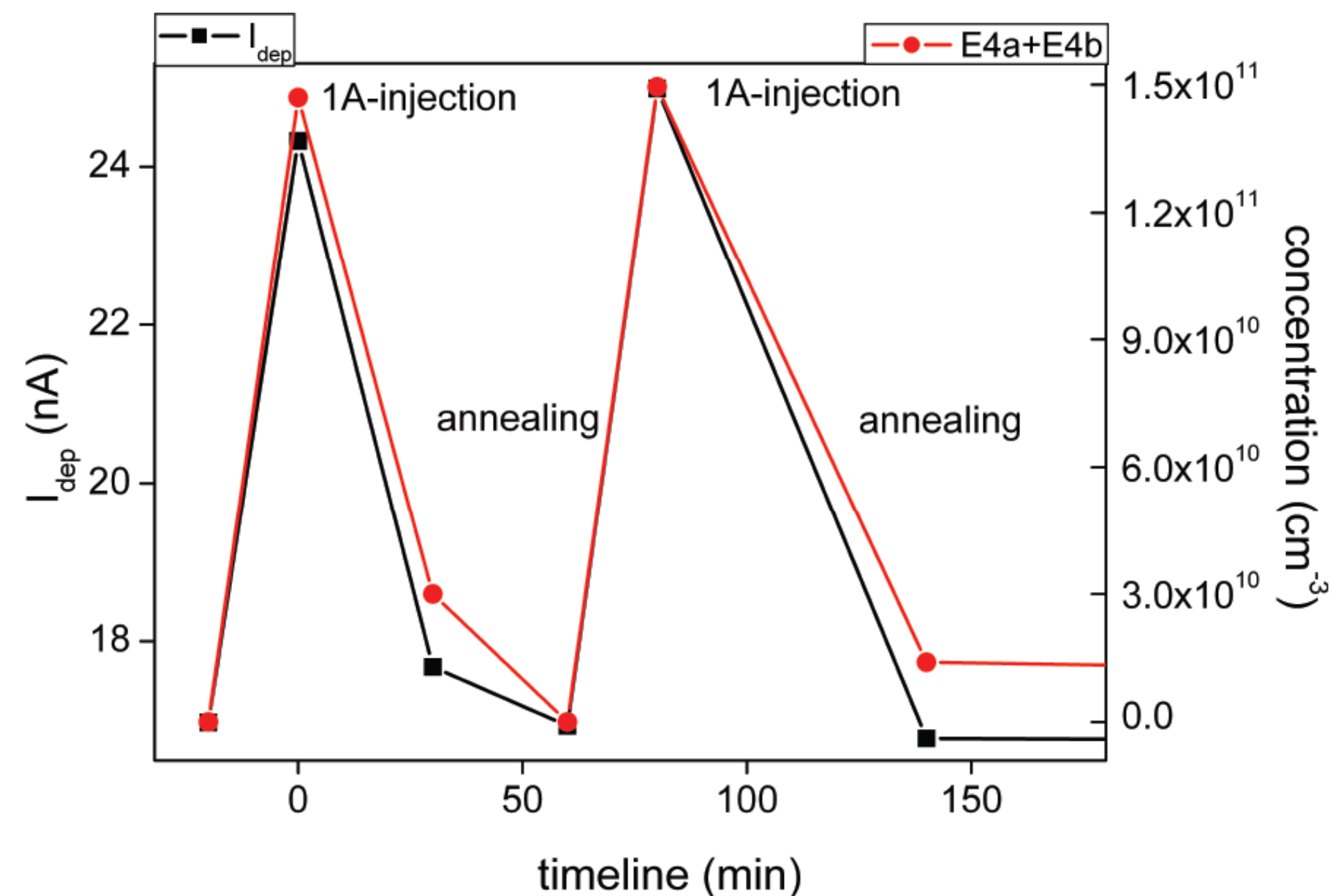
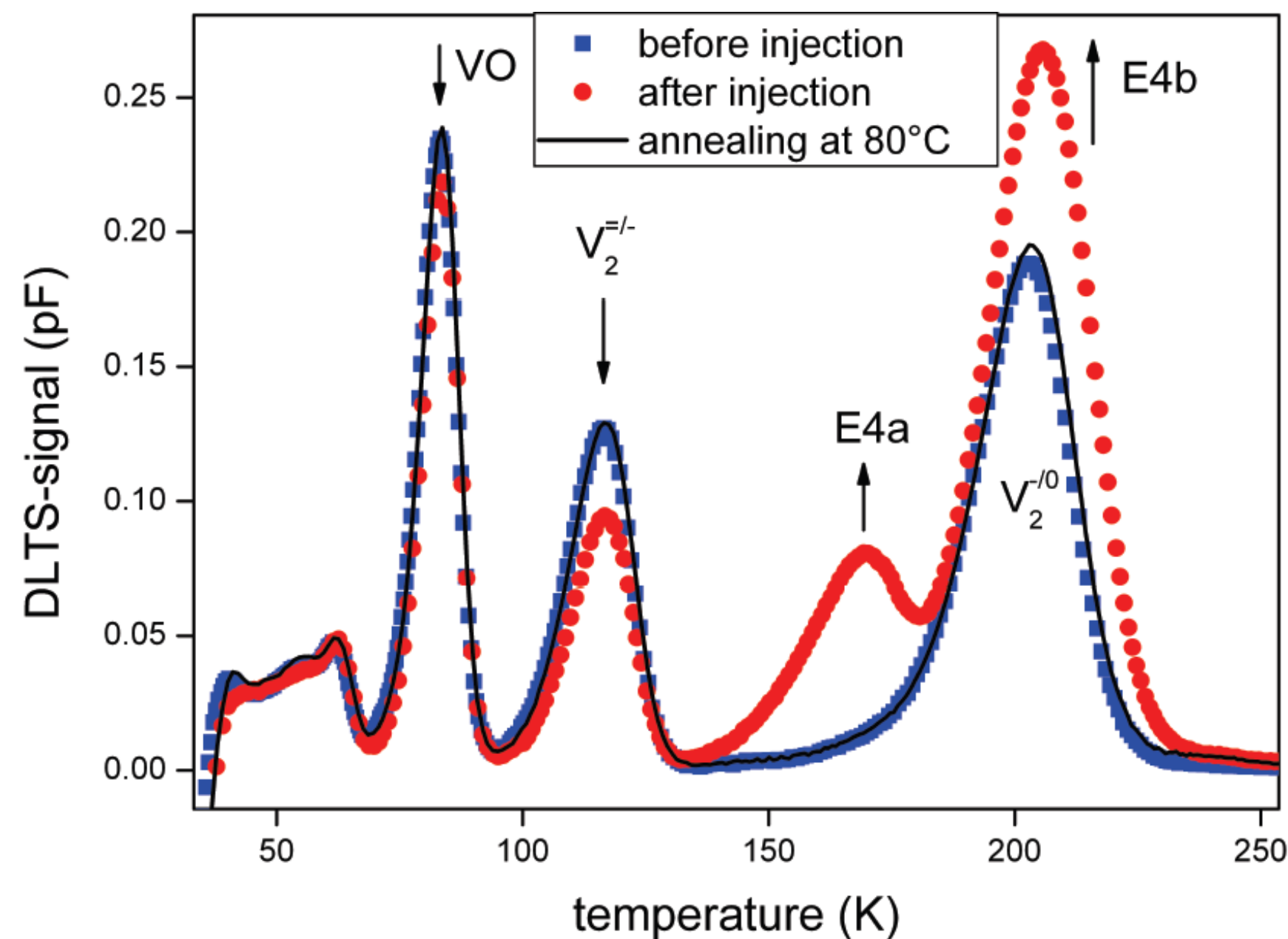
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Towards the Origin of the Leakage Current

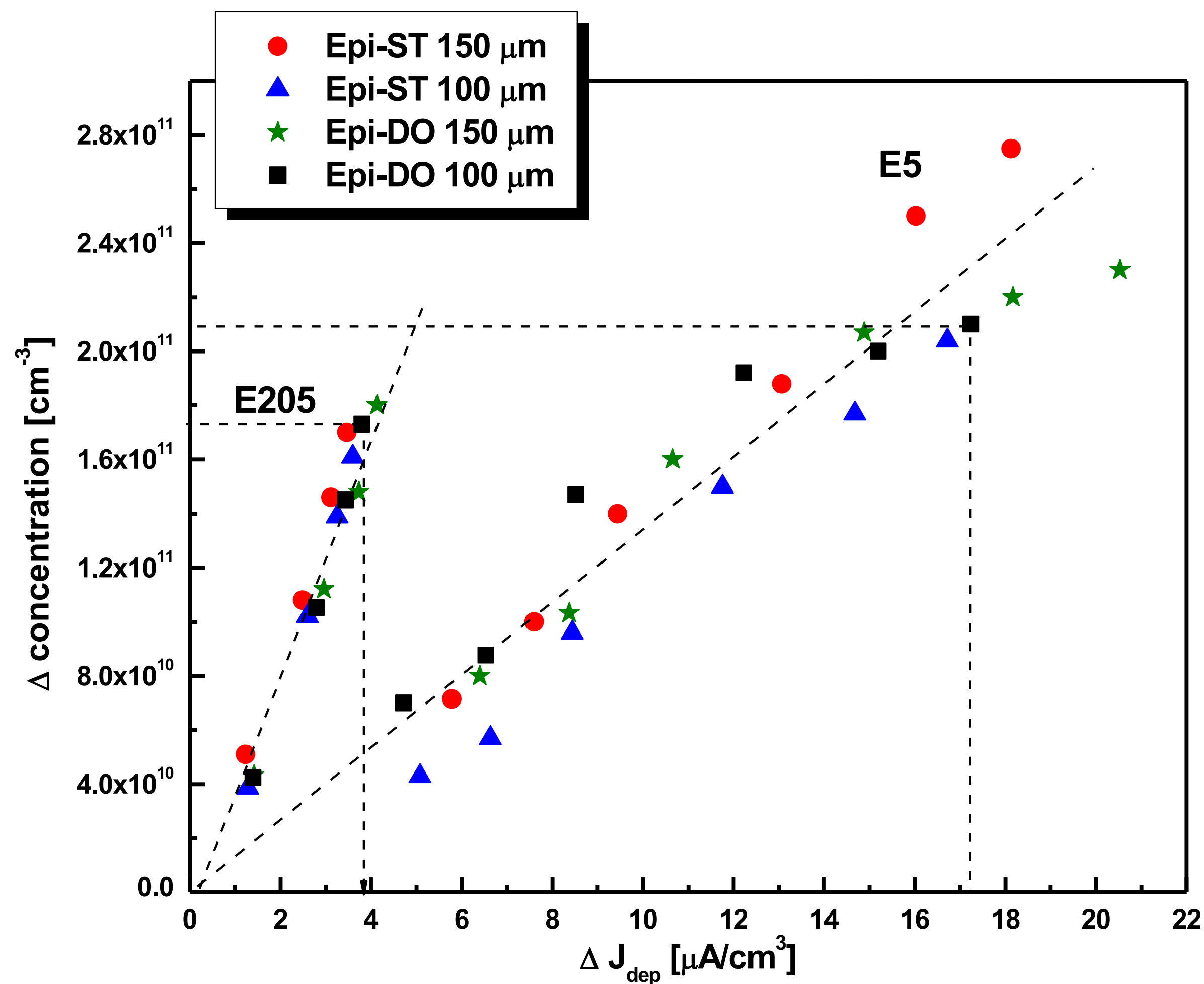


- Bistable defect E4/E5
- Correlation with leakage current found
 - What type of defect is this?
 - How large is the impact on the leakage current?



[A.Junkes at RD50 Workshop May/June 2010]

Towards the Origin of the Leakage Current



- Annealing study

- Disentangle different defects through their different annealing behaviour (change of cluster-configuration happens at different activation energies; E5 till 100°C , E205 starting from 140°C)

- Change in defect concentration vs. change in leakage current

Good progress in understanding the origin of leakage current

Work in progress...